

MAS 35x9F DATA SHEET

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MPEG Layer 2/3, AAC Audio Decoder, G.729 Annex A Codec

Release Note: Revision bars indicate significant changes to the previous edition. This data sheet applies to the MAS 35x9F version B4.

1. Introduction

The MAS 35x9F is a single-chip, low-power MPEG layer 2/3 and MPEG2-AAC audio stereo decoder. It also contains the G.729 Annex A speech compression and decompression technology for use in memory-based or broadcast applications. Additional functionality is achievable via download software (e.g., CELP voice decoder, Micronas SC4 (ADPCM) encoder/decoder).

The MAS 35x9F decoding block accepts compressed digital data streams as serial bit streams or in parallel format, and provides serial PCM and S/PDIF output of decompressed audio. In addition to the signal processing function, the IC incorporates a high-performance stereo D/A converter, headphone amplifiers, a stereo A/D converter, a microphone amplifier, and two DC/DC converters.

Thus, the MAS 35x9F provides a true "all-in-one" solution that is ideally suited for highly optimized memory-based portable music players with integrated speech recording and playback function.

In MPEG 1 (ISO 11172-3), three hierarchical layers of compression have been standardized. The most sophisticated and complex, layer 3, allows compression rates of approximately 12:1 for mono and stereo signals while still maintaining CD audio quality. Layer 2 (widely used, e.g., in DVD) achieves a compression of 8:1 without significant losses in audio quality.

The MAS 35x9F supports the "Advanced Audio Coding" (AAC) that is defined as a part of MPEG 2. AAC provides compression rates up to 16:1. It defines several profiles for different applications. This IC decodes the "low complexity profile" that is especially optimized for portable applications.

The MAS 35x9F also implements a voice encoder and decoder that is compliant to the ITU Standard G.729 Annex A.

SC4 is a proprietary Micronas speech codec technology that can be downloaded to the MAS 35x9F, to allow recording and playing back speech at various sampling rates.

1.1. Features

Firmware

- MPEG 1/2 layer 2 and layer 3 decoder
- Extension to MPEG 2 layer 3 for low sampling rates ("MPEG 2.5")
- Extraction of MPEG Ancillary Data
- MPEG 2 AAC decoder (low-complexity profile)
- Micronas G.729 Annex A speech compression and decompression
- Master or slave clock operation
- Adaptive bit rates (bit rate switching)
- Intelligent power management (processor clock is dependent on sampling frequencies)
- SDMI-compliant security technology
- Stereo channel mixer
- Bass, treble, and loudness function
- Micronas Bass (MB)
 - Automatic Volume Control (AVC)

Interfaces

- Two serial asynchronous interfaces for bit streams and uncompressed digital audio
- Parallel handshake bit stream input
- Serial audio output via I²S and related formats
- S/PDIF data input and output
- Controlling via I²C interface

Hardware Features

- Two independent embedded DC/DC converters, (e.g., for DSP and flash RAM supply)
- Low DC/DC converter start-up voltage (0.9 V)
- DC converter efficiency up to 95%
- Battery voltage monitor
- Low supply voltage down to 2.2 V
- Low power dissipation, e.g., 87 mW (128kBit/s, 44.1 kHz, Headphone playback)
- High-performance RISC DSP core
- On-chip crystal oscillator
- Hardware power management and power-off functions
- Microphone amplifier
- Stereo A/D converter for FM/AM-radio and speech input
- CD quality stereo D/A converter
- Headphone amplifier
- Noise and power-optimized volume
- External clock or crystal frequency of 13...28 MHz
- Standby current < 10 μA

1.2. Features of the MAS 35x9F Family

Feature	3509	3519	3529	3539	3549	3559
Layer 3 Decoder	Х	Х	Х	Х		
G.729 Encoder/Decoder	Х	Х			Х	
AAC Decoder	Х		Х			Х

1.3. Application Overview

The following block diagram shows an example application for the MAS 35x9F in a portable audio player device. Besides a simple controller and the external flash memories, all required components are integrated in the MAS 35x9F. The MAS 35x9F supports both speech and radio quality audio encoding, as well as compressed-audio decoding tasks.

Fig. 1–1 depicts a portable power-optimized audio application. The two embedded DC/DC converters of the MAS 35x9F generate optimum power supply voltages for the DSP core and also for state-of-the art flash memories that typically require 2.7 to 3.3 V supply. The performance of the DC/DC converters reaches efficiencies of up to 95%.

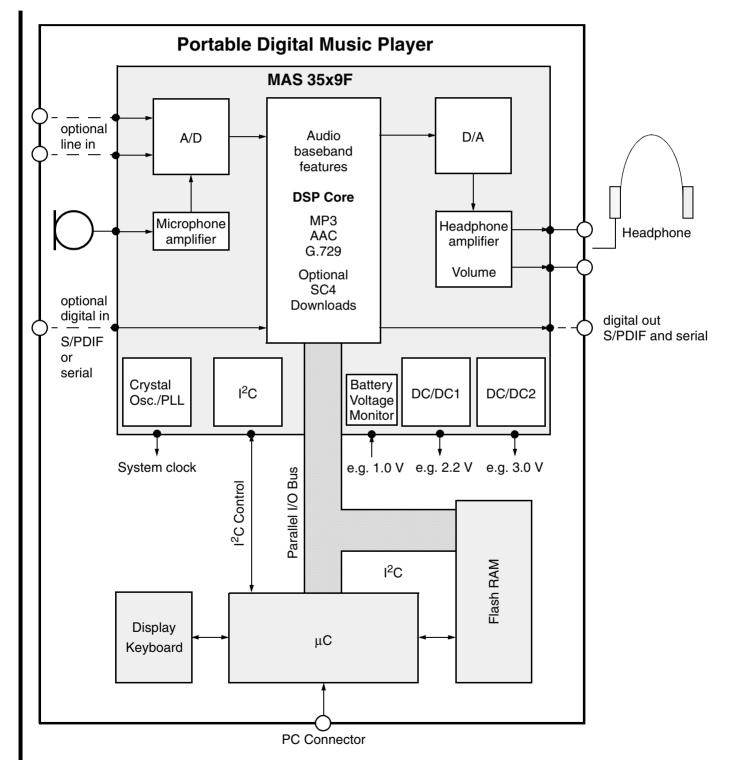


Fig. 1-1: Example of an application for the MAS 35x9F in a portable audio player device

MAS 35x9F DATA SHEET

2. Functional Description

2.1. Overview

The MAS 35x9F is intended for use in portable consumer audio applications. It receives parallel or serial data streams and decodes MPEG Layer 2 and 3 (including the low sampling frequency extensions) and MPEG 2 AAC. A low bit-rate speech codec, compliant to the ITU Standard G.729 Annex A, is integrated. Additional downloadable software modules (SDMI, other audio/speech encoders/decoders) are available on request.

2.2. Architecture of the MAS 35x9F

The hardware of the MAS 35x9F consists of a high-performance RISC Digital Signal Processor (DSP), and appropriate interfaces. A hardware overview of the IC is shown in Fig. 2–1.

2.3. DSP Core

The internal processor is a dedicated DSP for advanced audio applications.

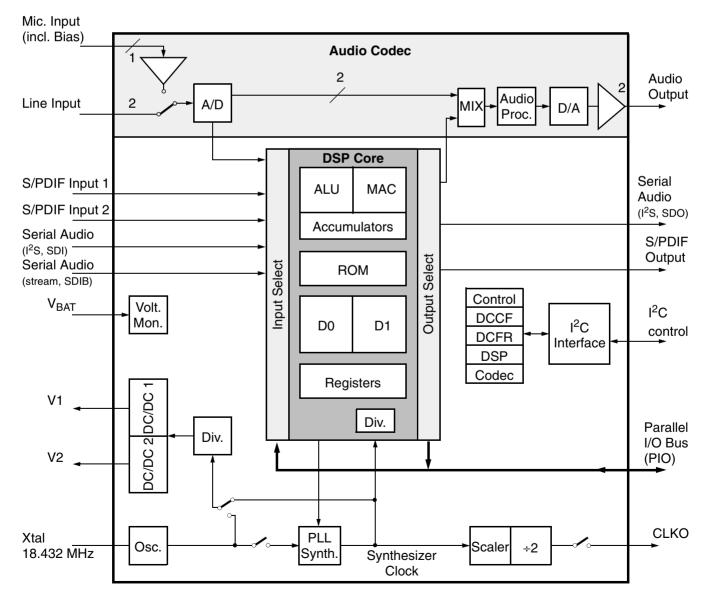


Fig. 2-1: The MAS 35x9F architecture

2.3.1. RAM and Registers

The DSP core has access to two RAM banks denoted D0 and D1. All RAM addresses can be accessed in a 20-bit or a 16-bit mode via I²C bus. For fast access of internal DSP states the processor core has an address space of 256 data registers which also can be accessed via I²C bus. For more details, please refer to Section 3.3. on page 26.

2.3.2. Firmware and Software

2.3.2.1. Internal Program ROM and Firmware, MPEG-Decoding

The firmware implemented in the program ROM of the MAS 35x9F provides MPEG 1/2 Layer 2, MPEG 1/2/2.5 Layer 3 and MPEG 2 AAC-decoding as well as a G.729 encoder and decoder.

The DSP operating system starts the firmware in the "Application Selection Mode". By setting the appropriate bit in the Application Select memory cell (see Table 3–8 on page 31), the MPEG audio decoder or the G.729 Codec can be activated.

The MPEG decoder provides an automatic standard detection mode. If all MPEG audio decoders are

selected, the Layer 2, Layer 3 or AAC bit stream is recognized and decoded automatically.

To add/remove MPEG layers while running in MPEG decoding mode (e.g. Layer 2, Layer 3 (0x0c) to Layer 2, Layer 3, AAC (0x1c)), the application selection has to be reset before writing the new value.

For general control purposes, the operation system provides a set of I²C instructions that give access to internal DSP registers and memory areas.

An auxiliary digital volume control and mixer matrix is applied to the digital stereo audio data. This matrix is capable of performing the balance control and a simple kind of stereo basewidth enhancement. All four factors LL, LR, RL, and RR are adjustable, please refer to Fig. 3–3 on page 43.

2.3.2.2. Program Download Feature

The standard functions of the MAS 35x9F can be extended or substituted by downloading up to 4 kWords (1 Word = 20 bits) of program code and additionally up to 4 kWords of coefficients into the internal RAM.

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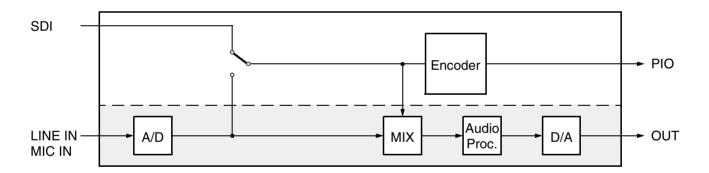


Fig. 2-2: Encoder signal flow

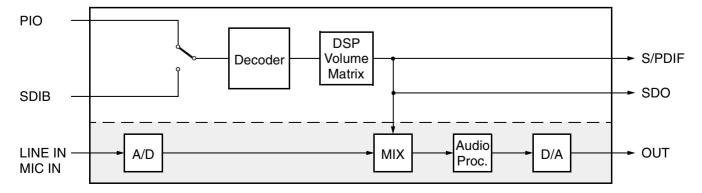


Fig. 2-3: Decoder signal flow

2.4. Audio Codec

A sophisticated set of audio converters and sound features has been implemented to comply with various kinds of operating environments that range up to highend equipment (see Fig. 2–4).

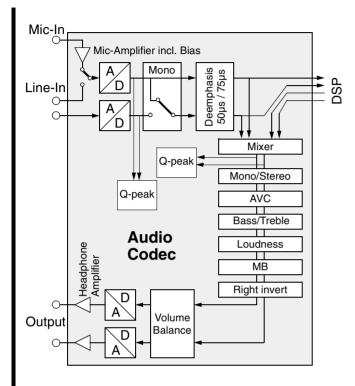


Fig. 2-4: Signal flow block diagram of Audio Codec

2.4.1. A/D Converter and Microphone Amplifier

A pair of A/D converters is provided for recording or loop-through purposes. In addition, a microphone amplifier including voltage supply function for an electret type microphone has been integrated.

2.4.2. Baseband Processing

The several baseband functions are applied to the digital audio signal immediately before D/A conversion.

2.4.2.1. Bass, Treble, and Loudness

Standard baseband functions such as bass, treble, and loudness are provided (refer to Table 3–16 for details).

2.4.2.2. Micronas Bass (MB)

The Micronas Bass system (MB) was developed to extend the frequency range of loudspeakers or headphones below the cutoff frequency of the speakers. Apart from dynamically amplifying the low-frequency bass signals, the MB exploits the psycho-acoustic phenomenon of the 'missing fundamental'. Adding harmonics of the frequency components below the cutoff frequency gives the impression of actually hearing the low frequency fundamental, while at the same time retaining the loudness of the original signal. Due to the parametric implementation of the MB, it can be customized to create different bass effects and adapted to loudspeaker characteristics various (see Section 3.4.4. and Table 3-16).

2.4.2.3. Automatic Volume Control (AVC)

In a collection of tracks from different sources fairly often the average volume level varies. Especially in a noisy listening environment the user must adjust the volume to comfortably enjoy listening. The Automatic Volume Correction (AVC) solves this problem by equalizing the volume level.

To prevent clipping, the AVC's gain decreases quickly in dynamic boost conditions. To suppress oscillation effects, the gain increases rather slowly for low level inputs. The decay time is programmable by means of the AVC register (see Table 3–16 on page 45).

For input levels of -18 dBr to 0 dBr, the AVC maintains a fixed output level of -9 dBr. Fig. 2–5 shows the AVC output level versus its input level. For volume and baseband registers set to 0 dB, a level of 0 dBr corresponds to full scale input/output.

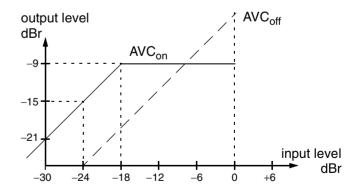


Fig. 2-5: Simplified AVC characteristics

2.4.2.4. Balance and Volume

To minimize quantization noise, the main volume control is automatically split into a digital and an analog part. The volume range is -114...+12 dB with an additional mute position. A balance function is provided.

2.4.3. D/A Converters

One pair of Micronas' unique multibit sigma-delta D/A converters is used to convert the audio data with high linearity and a superior S/N. In order to attenuate high-frequency noise caused by noise-shaping, internal low-pass filters are included. They require additional external capacitors between pins FILTx and OUTx (see Section 5.1. on page 89).

2.4.4. Output Amplifiers

The integrated output amplifiers are capable of directly driving stereo headphones or loudspeakers of 16 to 32 Ω impedance via 22 Ω series resistors. If more output power is required, the right output signal can be inverted and a single loudspeaker can be connected as a bridge between pins OUTL and OUTR. In this case, the source should be set to mono for optimized power.

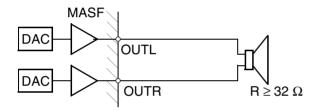


Fig. 2-6: Bridge operation mode

2.5. Clock Management

The MAS 35x9F is driven by a single crystal-controlled clock with a frequency of 18.432 MHz. It is possible to drive the MAS 35x9F with other reference clocks. In this case, the nominal crystal frequency must be written into memory location D0:348. The crystal clock acts as a reference for the embedded synthesizer that generates the internal clock.

For compressed audio data reception, the MAS 35x9F may act either as the clock master (Demand Mode) or as a slave (Broadcast Mode) as defined by bit[1] in IOControlMain memory cell (see Table 3–8 on page 31). In both modes, the output of the clock synthesizer depends on the sample rate of the decoded data stream as shown in Table 2–1.

In the BROADCAST MODE (PLL on), the incoming audio data controls the clock synthesizer via a PLL.

In the DEMAND MODE (PLL off) the MAS 35x9F acts as the system master clock. The <u>data</u> transfer is triggered by a demand signal at pin EOD.

2.5.1. DSP Clock

The DSP clock has a separate divider. In order to reduce the power consumption, it is set to the lowest acceptable rate of the synthesizer clock which is capable to allow the processor core to perform all tasks.

2.5.2. Clock Output At CLKO

If the DSP or audio codec functions are enabled (bits[11] or [10] in the Control Register at I^2C subaddress $6A_{hex}$), the reference clock at pin CLKO is derived from the synthesizer clock.

Dependent on the sample rate of the decoded signal a scaler is applied which automatically divides the clock-out by 1, 2, or 4, as shown in Table 2–1. An additional division by 2 may be selected by setting bit[17] of the OutClkConfig memory cell (see Table 3–8 on page 31). The scaler can be disabled by setting bit[8] of this cell.

The controlling at OutClkConfig is only possible as long as the DSP is operational (bit[10] of the Control Register). Settings remain valid if the DSP is disabled by clearing bit[10].

Table 2–1: Settings of bits[8] and [17] in OutClkConfig and resulting CLKO output frequencies

	Output Frequency at CLKO/MHz									
f _s /kHz	Synth. Clock bit[8]=1		er On bit[17]=0	Extra D	r Plus Division bit[17]=1					
48	24.576	512·f _s	24.576	256·f _s	12.288					
44.1	22.5792	O12 is	22.5792	200 is	11.2896					
32	24.576	768·f _s	24.576	384·f _s	12.288					
24	24.070	512·f _s	12.288	256·f _s	6.144					
22.05	22.5792	O12 is	11.2896	200 is	5.6448					
16	24.576	768·f _s	12.288	384·f _s	6.144					
12	24.070	512·f _s	6.144	256·f _s	3.072					
11.025	22.5792	O I Z IS	5.6448	200 is	2.8224					
8	24.576	768·f _s	6.144	384·f _s	3.072					

2.6. Power Supply Concept

The MAS 35x9F was designed for minimal power dissipation. In order to optimize the battery management in portable players, two DC/DC converters were implemented to supply the complete portable audio player with regulated voltages.

2.6.1. Power Supply Regions

The MAS 35x9F has five power supply regions.

The VDD/VSS pin pair supplies all digital parts including the DSP core, the XVDD/XVSS pin pair is connected to the digital signal pin output buffers, the AVDD0/AVSS0 supply is for the analog output amplifiers, AVDD1/AVSS1 for all other analog circuits like clock oscillator, PLL circuits, system clock synthesizer and A/D and D/A converters. The I²C interface has an own supply region via pin I2CVDD. Connecting this to the microcontroller supply assures that the I²C bus always works as long as the microcontroller is alive so that the operating modes can be selected.

Beside these regions, the DC/DC converters have start-up circuits of their own which get their power via pin VSENSx.

2.6.2. DC/DC Converters

The MAS 35x9F has two embedded high-performance step-up DC/DC converters with synchronous rectifiers to supply both the DSP core itself and external circuitry such as a controller or flash memory at two different voltage levels. An overview is given in Fig. 2–7 on page 13.

The DC/DC converters are designed to generate an output voltage between 2.0 V and 3.5 V which can be programmed separately for each converter via the I^2C interface (see table 3.3). Both converters are of bootstrapped type allowing to start up from a voltage down to 0.9 V for use with a single battery or NiCd/NiMH cell. The default output voltages are 3.0 V. Both converters are enabled with a high level at pin DCEN and enabled/disabled by the I^2C interface.

The MAS 35x9F DC/DC converters feature a constant-frequency, low noise pulse width modulation (PWM) mode and a low quiescent current, pulse frequency modulation (PFM) mode for improved efficiencies at low current loads. Both modes – PWM or PFM – can be selected independently for each converter via I²C interface. The default mode is PWM.

In PWM mode the switching frequency of the power-MOSFET-switches is derived from the crystal oscillator. Switching harmonics generated by constant frequency operation are consistent and predictable.

When the audio codec is enabled, the switching frequency of the converters is synchronised to the audio codec clock to avoid interferences into the audio band. The actual switching frequency can be selected via the I²C-interface between 300 kHz and 580 kHz (for details see DCFR Register in Table 3–3 on page 23).

In the PFM operation mode, the switching frequency is controlled by the converters themselves. It will be just high enough to service the output load, thus resulting in the best possible efficiency at low current loads. The PFM mode does not need a clock signal from the crystal oscillator. If both converters do not use the PWM-mode, the crystal clock will be shut down as long it is not needed by other internal blocks.

The synchronous rectifier bypasses the external Schottky diode to reduce losses caused by the diode forward voltage providing up to 5% efficiency improvement. By default, the P-channel synchronous rectifier switch is turned on when the voltage at pin(s) DCSOn exceeds the converter's output voltage at pin(s) VSENSn, and is turned off when the inductor current drops below a threshold. If one or both converters are disabled, the corresponding P-channel switch will be turned on, connecting the battery voltage to the DC/DC converters output voltage at pin VSENSn. However, it is possible to individually disable both synchronous rectifier switches by setting the corresponding bits (bit[8] and [0] in DCCF-register).

If both DC/DC-converters are off, a high signal may be applied at pin DCEN. This will start the converters in their default mode (PWM with 3.0 V output voltage). The PUP signal will change from low to high when both converters have reached their nominal output voltage and will return to low when both converters output voltages have dropped 200 mV below their programmed output voltage. The signal at pin PUP can be used to control the reset of an external microcontroller (see Section 2.10.2. on page 17 for details on the start-up procedure).

If only DC/DC-converter 1 is used, the output of the unused converter 2 (VSENS2) must be connected to the output of converter 1 (VSENS1) to make the PUP signal work properly. Also, if a DC/DC-converter is not used (no inductor connected), the pin DCSO must be left vacant.

2.6.3. Power Supply Configurations

One of the following supply configurations may be used:

- Power-optimized solution (recommended operation). DC/DC 1 (e.g. 2.2 V) drives the MAS 35x9F DSP and the audio circuitry, DC/DC 2 (e.g. 2.7 V) supplies controller and flash (see Fig. 2–8 on page 14)
- Volume-optimized solution. DC/DC 1 (e.g. 2.7 V) supplies controller, flash and MAS 35x9F audio parts, DC/DC 2 generates e.g. 2.2 V for the MAS 35x9F DSP (see Fig. 2–9 on page 14).
- Minimized external components. DC/DC 1 operates on, e.g., 2.7 V and feeds all components, DC/DC 2 remains off (see Fig. 2–10 on page 14).
- External power supply. All components are powered by an external source, no DC/DC converter is used (see Fig. 2–11 on page 14).

If DC/DC converter 1 is used, it must supply the analog circuits (pins AVDD0, AVDD1) of the MAS 35x9F.

If only one DC/DC converter is required, DC/DC1 must be used. Pin DCSO2 must be left vacant, pin VSENS2 should be connected to pin VSENS1.

If the DC/DC converters are not used, pin DCEN must be connected to VSS, DCSOx must be left vacant.

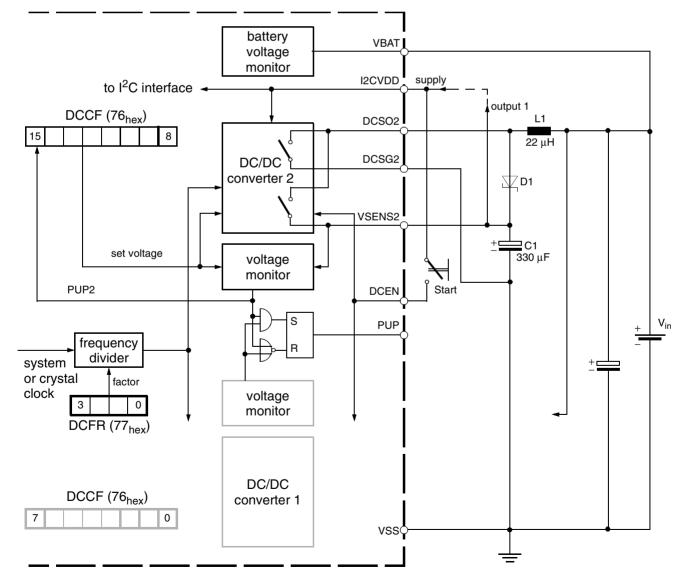
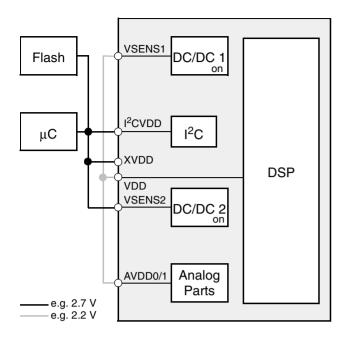
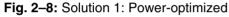


Fig. 2-7: DC/DC converter overview. The DCEN input must be connected to pin I2CVDD via start-up push button.

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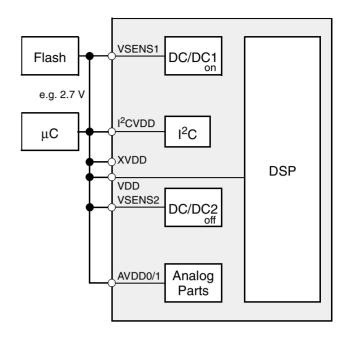


Fig. 2-10: Solution 3: Minimized components

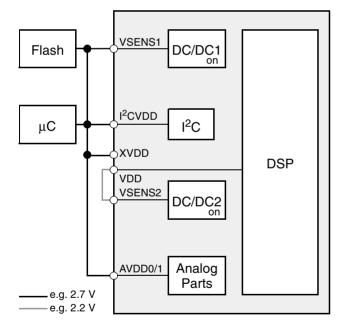


Fig. 2-9: Solution 2: Volume-optimized

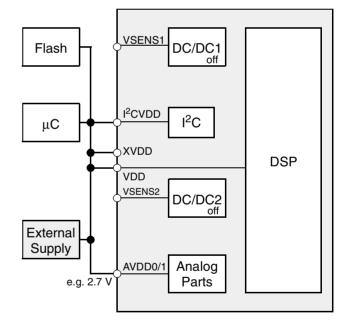


Fig. 2-11: Solution 4: External power supply

Micronas

2.7. Battery Voltage Supervision

Independent of the DC/DC converters, a battery voltage supervision circuit (at pin VBAT) is provided. It can be programmed to supervise one or two battery cells. The voltage is measured by subsequently setting a series of voltage thresholds and checking the respective comparison result in register 77_{hex}.

2.8. Interfaces

The MAS 35x9F uses an I²C control interface, a serial input interface for MPEG bit streams, and digital audio output interfaces for the decoded audio data (I²S and S/PDIF). S/PDIF input is available after Software download. A parallel I/O interface (PIO) may be used for fast data exchange.

2.8.1. I²C Control Interface

For controlling and program download purposes, a standard I^2C slave interface is implemented. A detailed description of all functions can be found in Section 3.

2.8.2. S/PDIF Input Interface

The S/PDIF interface receives a one-wire serial bus signal. In addition to the signal input pin SPDI1/SPDI2, a reference pin SPDIR is provided to support balanced signal sources or twisted pair transmission lines.

The synchronization time on the input signal is < 50 ms.

S/PDIF input is not supported for MPEG 1/2 Layer 2/3 and MPEG 2 AAC.

Micronas has developed a download software for flexible usage of the S/PDIF I/O and SDI/SDO interfaces. It is described in Download Software Supplement I2SPDIF (6251-505-1PDS).

2.8.3. S/PDIF Output

The S/PDIF output of the baseband audio signals is implemented at pin SPDO since version B4.

The channel status bits can be set as described in Table 3–8.

2.8.4. Multiline Serial Audio Input (SDI, SDIB)

There are two multiline serial audio input interfaces (SDI, SDIB) each consisting of the three pins SI(B)C, SI(B)I, and SI(B)D. The standard firmware only supports SDIB for bit-stream signals, while PCM-inputs should be routed to SDI.

The interfaces can be configured as continuous bitstream or word-oriented inputs. For the MPEG bit streams, the word strobe pin SIBI must always be connected to V_{SS} ; bits must be sent MSB first as created by the encoder.

If the download software (refer to Download Software Supplement I2SPDIF (6251-505-1PDS)) is used, the interface acts as an I^2 S-type with SI(B)I as a word-strobe for PCM data.

For the Demand Mode (see Section 2.5.), the signal clock coming from the data source must be higher than the <u>nominal</u> data transmission rate (e.g. 128 kbit/s). Pin EOD is used to interrupt the data flow whenever the input buffer of the MAS 35x9F is filled.

For controlling details, please refer to Table 3–8 on page 31.

2.8.5. Multiline Serial Output (SDO)

The serial audio output interface of the MAS 35x9F is a standard I^2S -like interface consisting of the data lines SOD, the word strobe SOI and the clock signal SOC. It is possible to choose between two standard interface configurations (16-bit data words with word strobe time offset or 32-bit data words with inverted SOI signal).

If the serial output generates 32 bits per audio sample, only the first 20 bits will carry valid audio data. The 12 trailing bits are set to zero by default.

2.8.6. Parallel Input/Output Interface (PIO)

The parallel interface of the MAS 35x9F consists of the 8 data lines PI12...PI19 (MSB) and the control lines PCS, PR, PRTR, PRTW, and EOD. It can be used for data exchange with an external memory, for fast program download and for other special purposes as defined by the DSP software.

For MPEG data input, the PIO interface is activated by setting bits[9] and [8] in D0:346 to 01. For the handshake protocol, please refer to Section 4.6.2.8. on page 80.

2.9. MPEG Synchronization Output

The signal at pin SYNC is set to '1' after the internal decoding for the MPEG header has been finished for one frame. The rising edge of this signal can be used as an interrupt input for the controller that triggers the read out of the control information and ancillary data. As soon as the MAS 35x9F has received the SYNC reset command (see Section 4.6.2.6. on page 77), the SYNC signal is cleared. If the controller does not issue a reset command, the SYNC signal returns to '0' as soon as the decoding of the next MPEG frame is started. MPEG status and ancillary data become invalid until the frame is completely decoded and the signal at pin SYNC rises again. The controller must have finished reading all MPEG information before it becomes invalid. The MPEG Layer 2/3 frame lengths are given in Table 2-2. AAC has no fixed frame length.

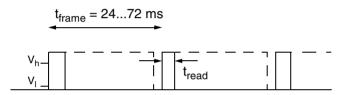


Fig. 2–12: Schematic timing of the signal at pin SYNC. The signal is cleared at $t_{\rm read}$ when the controller has

issued a Clear SYNC Signal command (see Section 4.6.2.6. on page 77). If no command is issued, the signal returns to '0' just before the decoding of the next MPEG frame.

Table 2-2: Frame length in MPEG Layer 2/3

f _s /kHz	Frame Length Layer 2	Frame Length Layer 3
48	24 ms	24 ms
44.1	26.12 ms	26.12 ms
32	36 ms	36 ms
24	24 ms	24 ms
22.05	26.12 ms	26.12 ms
16	36 ms	36 ms
12	not available	48 ms
11.025	not available	52.24 ms
8	not available	72 ms

2.10. Default Operation

This sections refers to the standard operation mode "power-optimized solution" (see Section 2.6.3.).

2.10.1. Stand-by Functions

After applying the battery voltage, the system will remain stand-by, as long as the DCEN pin level is kept low. Due to the low stand-by current of CMOS circuits, the battery may remain connected to DCSOn/VSENSn at all times.

2.10.2.Power-Up of the DC/DC Converters and Reset

The battery voltage must be applied to pin DCSOn via the 22 μ H inductor and, furthermore, to the sense pin VSENSn via a Schottky diode (see Fig. 2–7 on page 13).

For start-up, the pin DCEN must be connected via an external "start" push button to the I2CVDD supply, which is equivalent to the battery supply voltage (> 0.9 V) at start-up.

The supply at DCEN must be applied until the DC/DC converters have started up (signal at pin PUP) and then removed for normal operation.

As soon as the output voltage at VSENSn reaches the default voltage monitor reset level of 3.0 V, the respective internal PUPn bit will be set. When both PUPn bits are set, the signal at pin PUP will go high and can be used to start and reset the microcontroller.

Before transmitting any I^2C commands, the controller must issue a power-on reset to pin POR. The separate supply pin I^2C on the separate supply pin I^2C on the power supply pin the DSP or the audio codec. Now the desired supply voltage can be programmed at I^2C subaddress I^2C subaddres

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2.10.2.1.Important Advice for Turn-on and Operating Voltage

Before the 2.2 V are programmed at the DCDC converter, DSP+Codec must be enabled.

Operating and Turn-Off is possible down to 2.2 V.

The sequence should be similar to the following:

- 1. Start DCDC
- 2. Set DCDC to 2.5 V
 Turn on DSP+Codec
 Write App-Select memory cell
 Read App-Running Mem cell
 If okay: Set DCDC to 2.2 V
 Set other mem cells
 Set other codec registers
- 3. Demute...send data
- 4. Mute...stop data.....loop "3)" "4)"...
- 5. Turn off DSP+Codec goto "2)" etc.....

The signal at pin PUP will return to low only when both PUPn flags ($\rm I^2C$ subaddress $\rm 76_{hex}$) have returned to zero. Care must be taken when changing both DC/DC output voltages to higher values. In this case, both output voltages are momentarily insufficient to keep the PUPn flags up; the resulting dip in the signal at the PUP pin may, in turn, reset the microcontroller. To avoid this condition, only one DC/DC output voltage should be changed at a time. Before modifying the second voltage, the microcontroller must wait for the PUPn flag of the first voltage to be set again.

If only DC/DC converter 1 is used, the reference voltage of the second, unused converter should be set to a lower value than that of converter 1, and its pin VSENS2 should be connected to VDD.

The operating mode pulse width modulation, or pulse frequency modulation, are controlled at I^2C subaddress 76_{hex} , the operating frequency at I^2C subaddress 77_{hex} .

2.10.3. Reset Signal Specification

After power-up, a reset signal should be applied to the pin \overline{POR} by the microcontroller as follows:

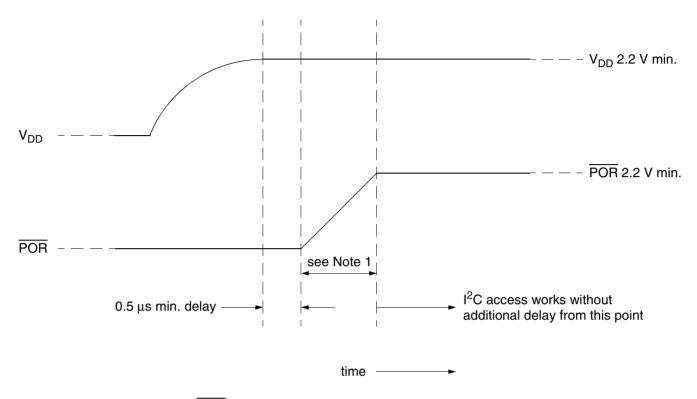


Fig. 2–13: Reset signal at pin POR

Note: The slew rate of POR should be as high as possible, but **must be glitch-free in any case**.

Slew rate typ.: 1 μs for 10% to 90% level transition, Slew rate max.: 20 μs for 10% to 90% level transition.

2.10.4. Control of the Signal Processing

Before starting the DSP, the controller should check for a sufficient voltage supply (respective flag PUPn at I^2C subaddress 76_{hex}). The DSP is enabled by setting the appropriate bit in the Control register (I^2C subaddress $6A_{hex}$). The nominal frequency of the crystal oscillator must be written into D0:348. After an initialization phase of 5 ms, the DSP data registers can be accessed via I^2C .

Input and output control is performed via memory location D0:346 and D0:347. The serial input interface SDIB is the default. The decoded audio can be routed to either the S/PDIF, the SDO and the analog outputs. The output clock signal at pin CLKO is defined in D0:349.

All changes in the D0 memory cells become effective synchronously upon setting the LSB of Main I/O Control (see Table 3–8 on page 31). Therefore, this cell should always be written last.

The digital volume control (see Table 3–8 on page 31) is applied to the output signal of the DSP. The decoded audio data will be available at the SPDO output interface in the next version.

The DSP does not have to be started if its functions are not required, e.g., for routing audio through the codec part of the IC via the A/D and the D/A converters.

2.10.5. Start-up of the Audio Codec

Before enabling the audio codec, the controller should check for a sufficient voltage supply (respective flag PUPn at I²C subaddress 76_{hex}).

The audio codec is enabled by setting the appropriate bit at the Control register (I 2 C subaddress $6A_{hex}$). After an initialization phase of 5 ms, the DSP data registers can be accessed via I 2 C. The A/D and the D/A converters must be switched on explicitly (register 00.00_{hex} at I 2 C subaddress $6C_{hex}$). The D/A converters may either accept data from the A/D converters or the output of the DSP, or a mix of both $^{1)}$ (register 00.06_{hex} and 00.07_{hex} at I 2 C subaddress $6C_{hex}$). Finally, an appropriate output volume (register 00.10_{hex} at I 2 C subaddress $6C_{hex}$) must be selected.

2.10.6. Power-Down

All analog outputs should be muted and the A/D and the D/A converters must be switched off (register 00 10_{hex} and 00 00_{hex} at I²C subaddress $6C_{hex}$). The DSP and the audio codec must be disabled (clear DSP_EN and CODEC_EN bits in the Control register, I²C subaddress $6A_{hex}$). By clearing both DC/DC enable flags in the Control register (I²C subaddress $6A_{hex}$), the microcontroller can power down the complete system.

¹⁾ mixer available in version A2 and later; in version A1, please use selector 00 $0F_{\rm hex}$.

3. Controlling

3.1. I²C Interface

Controlling between the MAS 35x9F and the external controller is done via an I²C slave interface.

3.1.1. Device Address

The device addresses are $3C/3E_{hex}$ (device write "DW") and $3D/3F_{hex}$ (device read, "DR") as shown in Table 3–1. The device address pair $3C/3D_{hex}$ applies if the DVS pin is connected to VSS, the device address pair $3E/3F_{hex}$ applies if the DVS pin is connected to I2CVDD.

Table 3-1: I²C device address

A7	A 6	A 5	A 4	А3	A2	A 1	W/R
0	0	1	1	1	1	DVS	0/1

I²C clock synchronization is used to slow down the interface if required.

3.1.2. I²C Registers and Subaddresses

The interface uses one level of subaddresses. The MAS 35x9F interface has 7 subaddresses allocated for the corresponding I^2C registers. The registers can be divided into three categories as shown in Table 3–2.

The address $6A_{hex}$ is used for basic control, i.e. reset and task select. The other addresses are used for data transfer from/to the MAS 35x9F.

The I^2C registers of the MAS 35x9F are 16 bits wide, the MSB is denoted as bit[15]. Transmissions via I^2C bus have to take place in 16-bit words (two byte transfers, MSB sent first); thus, for each register access, two 8-bit data words must be sent/received via I^2C bus.

3.1.3. Naming Convention

The description of the various controller commands uses the following formalism:

- Abbreviations used in the following descriptions:
 - a address
 - d data value
 - n count value
 - o offset value
 - r register number
 - x don't care
- Memory addresses, like D1:89f, are always in hexadecimal notation.
- A data value is split into 4-bit nibbles which are numbered beginning with 0 for the least significant

nibble.

- Data values in nibbles are always shown in hexadecimal notation.
- A hexadecimal 20-bit number **d** is written, e.g. as $\mathbf{d} = 17C63_{\text{hex}}$, its five nibbles are $d0 = 3_{\text{hex}}$, $d1 = 6_{\text{hex}}$, $d2 = C_{\text{hex}}$, $d3 = 7_{\text{hex}}$, and $d4 = 1_{\text{hex}}$.
- Variables used in the following descriptions:

I2C address:

DW3C/3E_{hex}l²C device write DR3D/3F_{hex}l²C device read

DSP core:

data_write68_{hex}DSP data write data_read69_{hex}DSP data read

codec_write6C_{hex}codec write codec_read6D_{hex}codec read

- Bus signals

S Start

P Stop

A ACK = Acknowledge N NAK = Not acknowledge

W Wait = I^2C clock line is held low

while the MAS 35x9F is processing

the current I2C command

- Symbols in the telegram examples

< Start Condition

> Stop

dd data bytes

xx ignore

All telegram numbers are hexadecimal, data originating from the MAS 35x9F are represented as gray letters.

Example:

<DW 68 dd dd > write data to DSP <DW 69 <DR dd dd > read data from DSP

Fig. 3–1 shows I²C bus protocols for write and read operations of the interface; the read operations require an extra start condition and repetition of the chip address with the device read command (DR). Fields with signals/data originating from the MAS 35x9F are marked by a gray background.

Note: In some cases the data reading process must be concluded by a NAK condition.

3.2. Direct Configuration Registers

The task selection of the DSP and the DC/DC converters are controlled in the direct configuration registers CONTROL, DCCF, and DCFR.

Table 3-2: I²C subaddresses

Sub- address (hex)	I ² C- Register Name	Function
Direct Co	nfiguration	
6A	CONTROL	Controller writes to MAS 35x9F CONTROL register
76	DCCF	Controller writes to first DC/DC configuration register
77	DCFR	Controller writes to second DC/DC configuration register
DSP Core	e Access	
68	data_write	Controller writes to MAS 35x9F DSP
69	data_read	Controller reads from MAS 35x9F DSP
Codec Ad	ccess	
6C	codec_write	Controller writes to MAS 35x9F codec regis- ter
6D	codec_read	Controller reads from MAS 35x9F codec regis- ter

3.2.1. Write Direct Configuration Registers

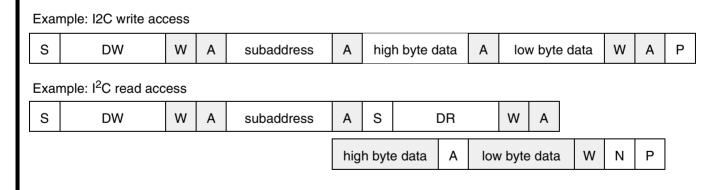
- 1											
	S	DW	W	Α	subaddr.	Α	d3,d2	Α	d1,d0	Α	Р

The write protocol for the direct configuration registers only consists of device address, subaddress and one 16-bit data word.

3.2.2. Read Direct Configuration Register

s	DW	W	Α	subaddr.	Α	S	D	R	W	Α		
						d3	,d2	Α	d1,	,d0	Ν	Р

To check the PUP1 and PUP2 power-up flags, it is necessary to read back the content of the direct configuration registers.



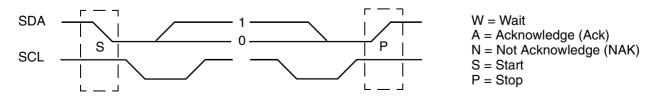


Fig. 3–1: Example of an I²C bus protocol for the MAS 35x9F (MSB first; data must be stable while clock is high)

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Table 3–3: Direct configuration registers

I ² C Sub- address (hex)	Function				Name
6A	Control Re	egister (re	eset value =	3000 _{hex})	CONTROL
	bit[15:14]	Analog	supply volta	ge range	
		Code 00 01 10 11	AGNDC 1.1 V 1.3 V 1.6 V reserved	recommended for voltage range of AVDD 2.0 2.4 V (reset) 2.4 3.0 V 3.0 3.6 V reserved	
	Higher volt		es permit hig	her output levels and thus a better signal-to-	
	bit[13] bit[12]		DC/DC 2 (re DC/DC 1 (re		
	Both DC/D	C convert	ters are swite	ched on by default with DCEN = high (1).	
	bit[11] bit[10]		and reset at		
	core and the The DSP of the analog	ne audio c an be left outputs (codec have to off if an aud set bit[15] in	coding and D/A conversion), both, the DSP of be enabled after the power-up procedure. it is signal is routed from the analog inputs to codec register 00 0F _{hex}). The audio codec gital inputs and outputs only.	
	bit[9] bit[8]	Reset of Reset D	codec OSP core		
	bit[7]			clock divider of 1.5 to 28 MHz) ¹⁾	
	bit[6:0]	Reserv	ed, must be	set to zero	

¹⁾ refer to Table 4–2 on page 68.
2) refer to Section 2.10.2.1.

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Table 3-3: Direct configuration registers, continued

I ² C Sub- address (hex)	Function DCCF Register (reset = 5050 _{hex})									
76										
	DC/DC Converter 2									
	bit[15] PUP2: Voltage monitor 2 flag (readback)									
	bit[14:11]	Converter	2 output volta	ge with resp	ect to VREF ²⁾					
	hi#[10]	Code 1111 1110 1101 1100 1011 1000 0111 0110 0101 0101 0101 00101 00101 00101 00101	Nominal output volt. 3.5 V 3.4 V 3.3 V 3.2 V 3.1 V 3.0 V 2.9 V 2.8 V 2.7 V 2.6 V 2.5 V 2.4 V 2.3 V 2.2 V	set level of PUP2 3.4 V 3.3 V 3.2 V 3.1 V 3.0 V 2.9 V 2.8 V 2.7 V 2.6 V 2.5 V 2.4 V 2.3 V 2.2 V 2.1 V	reset level of PUP2 3.3 V 3.2 V 3.1 V 3.0 V 2.9 V 2.8 V (reset) 2.7 V 2.6 V 2.5 V 2.4 V 2.3 V 2.2 V 2.1 V 2.0 V					
	bit[10]	Mode 1 0	pulse freque pulse width		ation (PFM) (PWM) (reset)					
	bit[9:8]	Reserved	, must be set to	o zero						
	The DC/DC converters are up-converters only. Thus, if the battery voltage is higher than the selected nominal voltage, the output voltage will exceed the nominal voltage.									
	DC/DC Co	nverter 1								
	bit[7]	PUP1: Vo	Itage monitor 1	flag (readb	ack)					
	bit[6:3]		1 output volta 14 to 11) ²⁾	ge at VSEN	S1 with respect to VREF					
	bit[2]	Mode 1 0	pulse freque		ation (PFM) (PWM) (reset)					
	bit[1:0]	Reserved	, must be set to	o zero						
	main refere	ence source	supplied via p	in AVDD1. 7	erter 1 is derived from the Therefore, if this DC/DC cone analog supply.					
		n the selecte			nus, if the battery voltage is put voltage will exceed the					

¹⁾ refer to Section 4.3.3. on page 59 2) refer to Section 2.10.2.1.

Table 3-3: Direct configuration registers, continued

					Name			
DCFR Reg	ister (reset	= 00 _{hex})			DCFR			
Battery Vo	Itage Monit	or						
bit[15]	Comparison 1 0	input volt						
bit[14]	Number o 0 1							
bit[13:10]	Voltage th 1111 1110 0010 0001 0000	1 cell 1.5 1.45 0.85 0.8	2 cells 3.0 V 2.9 V 1.7 V 1.6 V	ision off (reset)				
bit[9:8]	Reserved	, must be se	t to 0	, ,				
	n							
	d.							
DC/DC Co	nverter Fre	verter Frequency Control (PWM)						
bit[7:4]	Reserved	, must be se	t to 0					
bit[3:0]	Frequency	y of DC/DC	converter					
address 6A from the cr	0111 0110 0101 0100 0011 0000 1111 1110 1101 1101 1001 1001 1000 codec is not hex is zero),	315.1 323.4 332.1 341.3 351.1 361.4 372.4 384.0 396.4 409.6 423.7 438.9 455.1 472.6 491.5 512.0 ot enabled (bother) (bother) (nomina	r the DC/DC I 18.432 MHz	converters is directly derived:). Otherwise, the synthesize	d			
	bit[14] bit[14] bit[13:10] bit[9:8] The result it two threshold or switched or bit[7:4] bit[3:0]	Battery Voltage Monitorial bit[15] Comparison 1 0 0 0 1 1 bit[14] Number of 0 1 1 bit[13:10] Voltage the 1111 1110 0010 0001 0000 bit[9:8] Reserved The result is stable 1 m two thresholds is negligible. For power management switched off by setting DC/DC Converter Free bit[7:4] Reserved bit[3:0] Frequency Reference 0111 0110 0101 0100 0001 1111 1110 1101 1100 1101 1100 1101 1100 1101 1100 1101 1100 1101 1100 1101 1100 1101 1100 1101 1100 1101 1100 11001 11000 11000	1 input voltation input voltat	Battery Voltage Monitor bit[15] Comparison result (readback) 1	Battery Voltage Monitor			

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3.3. DSP Core

3.3.1. Access Protocol

The I²C data register is used to communicate with the internal firmware of the MAS 35x9F. It is readable (subaddress "data_read") and writable (subaddress "data_write") and also has a length of 16 bits. The data transfer is done with the most significant bit (m) first.

Table 3-4: Data register bit assignment

15	14	13	12	11	10	09	80	07	06	05	04	03	02	01	00
m															

A special command language is used that allows the controller to access the DSP registers and RAM cells and thus monitor internal states, set the parameters for the DSP firmware, control the hardware, and even provide a download of alternative software modules. The DSP commands consist of a "Code" which is sent to the I²C data register together with additional parameters.



Fig. 3-2: General core access protocol

Table 3–5 gives an overview over the different commands which the DSP Core receives via the I²C data register. The "Code" is always the first data nibble transmitted after the "data_write" subaddress byte. A second auxiliary code nibble is used for the short memory (16-bit) access commands.

The MAS 35x9F firmware scans the I²C interface periodically and checks for pending or new commands.

The commands are then executed by the DSP during its normal operation without any loss or interruption of the incoming data or outgoing audio data stream. However, due to some time critical firmware parts, a certain latency time for the response has to be expected at the locations marked with a "W" (= wait). The theoretical worst case response time does not exceed 4 ms. However, the typical response time is less than 0.5 ms.

Due to the 16-bit width of the I²C data register, all actions transmit telegrams with multiples of 16 data bits.

Table 3-5: Basic controller command codes

Code (hex)	Command	Function
03	Run	Start execution of an internal program. <i>Run</i> with start address 0 means freeze the operating system.
5	Read Ancillary Data	The controller reads a block of MPEG Ancillary Data from the MAS 35x9F
6	Fast Program Download	The controller downloads custom software via the PIO interface
7	Read IC Version	The controller reads the version information of the IC
а	Read from Register	The controller reads an internal register of the MAS 35x9F
b	Write to Register	The controller writes an internal register of the MAS 35x9F
С	Read D0 Memory	The controller reads a block of the DSP memory
d	Read D1 Memory	The controller reads a block of the DSP memory
е	Write D0 Memory	The controller writes a block of the DSP memory
f	Write D1 Memory	The controller writes a block of the DSP memory

3.3.2. Data Formats

The internal data word size is 20 bits. All RAM-addresses can be accessed in a 20-bit mode via I²C bus. Because of the 16-bit width of the I²C data register the full transfer of all 20 bits requires two 16-bit I²C words. Some commands only access the lower 16 bits of a cell. For fast access of internal DSP states the processor core also has an address space of 256 data registers.

The internal data format is a 20 bit two's complement denoted "r". If in some cases a fixed point notation "v" is necessary. The conversion between the two forms of notation is done as follows:

r = v*524288.0+0.5; $(-1.0 \le v < 1.0)$ v = r/524288.0; (-524288 < r < 524287)

3.3.2.1. Run and Freeze (Codes 0_{hex} to 3_{hex})



The Run command causes the start of a program part at address $\mathbf{a} = (a3,a2,a1,a0)$. Since nibble a3 is also the command code (see Table 3–5), it is restricted to values between 0 and 3. This command is used to start alternate code or downloaded code from a RAM-area that has been configured as program RAM.

If the start address is $1000_{hex} \le a < 3FFF_{hex}$ and the respective RAM area has been configured as program RAM (see Table 3–7 on page 30), the MAS 35x9F continues execution with a custom program already downloaded to this area.

Example 1: Start program execution at address 345_{hex}:

<DW 68 03 45>

Example 2: Start execution of a downloaded code at address 1000_{hex}:

<DW 68 10 00>

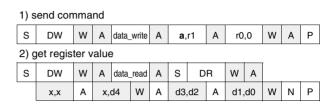
Freeze is a special run command with start address 0. It suspends all normal program execution. The operating system will enter an idle loop so that all registers and memory cells can be watched. This state is useful for operations like downloading code or contents of memory cells because the internal program cannot overwrite these values. This freezing will be required if alternative software is downloaded into the internal RAM of the MAS 35x9F.

Freeze has the following I²C protocol:

<DW 68 00 00>

The entry point of the default software will be accessed automatically after a reset, thus issuing a *Run* or *Freeze* command is only necessary for starting downloaded software or special program modules which are not part of the standard set.

3.3.2.2. Read Register (Code Ahex)



The MAS 35x9F has an address space of 256 DSP-registers. Some of the registers ($\mathbf{r} = r1,r0$ in the figure above) are direct control inputs for various hardware blocks, others control the internal program flow. In Table 3–7, the registers of interest are described in detail. In contrast to memory cells, registers cannot be accessed as a block but must always be addressed individually.

Example:

Read the content of register C8_{hex}:

<DW 68 ac 80> define register <DW 69 <DR xx xd dd dd > and read

3.3.2.3. Write Register (Code Bhex)

S	DW	W	Α	data_write	Α	b ,r1	Α	r0,d4	W	Α	
						d3,d2	Α	d1,d0	W	Α	Р

The controller writes the 20-bit value ($\mathbf{d} = d4,d3,d2,d1,d0$) into the MAS 35x9F register ($\mathbf{r} = r1,r0$). A list of registers needed for control purposes is given in Table 3–7.

Example: Writing the value 81234_{hex} into the register with the number AA_{hex} :

<DW 68 ba a8 12 34>

3.3.2.4. Read Memory (Codes Chex and Dhex)

The MAS 35x9F has 2 memory areas of 2048 words denoted D0 and D1. The memory areas D0 and D1 can be written by using the codes C_{hex} and D_{hex} , respectively.

1) send command (Read D0)

s	DW	W	Α	data_write	Α	c ,0	Α	0,0	W	Α	
						n3,n2	Α	n1,n0	W	Α	
						a3,a2	Α	a1,a0	W	Α	Р

2) get register value

S	DW	W	Α	data_	data_read		s	D	R	W	Α			
	x,x	Α	х,	x,d4		Α	d3,d2		Α	d1	,d0	W	Α	
				rep		for	n da	ata v	alue	s				
	X,X	Α	х,	d4	W	Α	d3	,d2	Α	d1	,d0	W	N	F

The Read D0 Memory command gives the controller access to all 20 bits of the D0/D1 memory cells. The telegram to read 3 words starting at location D1:100 is

3.3.2.5. Short Read Memory (Codes C4_{hex} and D4_{hex})

Because most cells in the user interface are only 16 bits wide, it is faster and more convenient to access the memory locations with a special 16-bit mode for reading:

1) send command (e.g. Short Read D0)

S	DW	W	Α	data_write	Α	C	,4	Α	0	,0	W	Α		
						n3	n3,n2 A r			,n0	w	Α		
							a3,a2 A a1,a0			W	Α	Р		
2) (2) get register value													
s	S DW W A data_read A				s	D	R	W	Α					
							d2	Α	d1	,d0	W	Α		
	repeat for					n da	ıta v	alue	s					
						d3	,d2	Α	d1	,d0	w	N	Р	

This command is similar to the normal 20 bit read command and uses the same command code C_{hex} and D_{hex} for D0 and D1 memory, respectively, however it is followed by a 4_{hex} rather than a 0_{hex} .

Example: Read 16 bits of D1:123 has the following I²C protocol:

<dw 00<="" 68="" d4="" th=""><th>read 16 bits from D1</th></dw>	read 16 bits from D1
00 01	1 word to be read
01 23	start address
<dw 69="" dr<="" td=""><td>start reading</td></dw>	start reading
dd dd >	and read

3.3.2.6. Write Memory (Codes E_{hex} and F_{hex})

The memory areas D0 and D1 can be written by using the codes E_{hex} and F_{hex} , respectively.

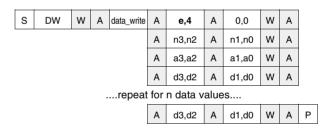
s	DW	W	A da	data_write		e ,0	Α	0,0	W	Α	
						n3,n2	Α	n1,n0	W	Α	
						a3,a2	Α	a1,a0	W	Α	
	x,x	Α	x,d4	4 W A		d3,d2	Α	d1,d0	W	Α	
		repeat for				n data v	alue	s			
	x,x	Α	x,d4	W	Α	d3,d2	Α	d1,d0	W	Α	Р

With the *Write D0/D1 Memory* command n 20-bit memory cells in D0 can be initialized with new data.

Example: Write 80234_{hex} to D1:456 has the following I²C protocol:

<3a 68 f0 00	write D1 memory
00 01	1 word to write
04 56	start address
00 08	$value = 80234_{hex}$
02 34>	

3.3.2.7. Short Write Memory (Codes E4_{hex} and F4_{hex})



For faster access only the lower 16 bits of each memory cell are written. The 4 MSBs of the cell are cleared. The command uses the same codes E_{hex} and F_{hex} for D0/D1 as for the 20-bit command but followed by a 4 rather than a 0.

3.3.2.8. Clear SYNC Signal (Code 5_{hex})



After a successful decoding of an MPEG frame the signal at pin SYNC rises and thus generates an interrupt event for the microcontroller. Issuing this command lets the signal at pin SYNC return to '0'.

3.3.2.9. Default Read

The *Default Read* command is the fastest way to get information from the MAS 35x9F. Executing the *Default Read* in a polling loop can be used to detect a special state during decoding.



The *Default Read* command immediately returns the lower 16 bit content of a specific RAM location as defined by the pointer D0:ffb. The pointer must be loaded before the first *Default Read* action occurs. If the MSB of the pointer is set, it points to a memory location in D1 rather than to one in D0.

Example: For watching D1:123 the pointer D0:ffb must be loaded with 8123_{hex} :

<DW	68	e0	00	write to D0 memory
	00	01		1 word to write
	Οf	fb		start address ffb
	00	08		value = 8
	01	23:	>	0123 _{hex}

Now the *Default Read* commands can be issued as often as desired:

<dw 69="" <dr<="" th=""><th><i>Default Read</i> command</th></dw>	<i>Default Read</i> command
dd dd >	16 bit content of the
	address as defined by the
	pointer
<dw 69="" <dr="" <i="">dd dd ></dw>	and do it again

3.3.2.10.Fast Program Download (Code 6hex)

s	DW	W	Α	data_write	Α	6 ,n2	Α	n1,n0	W	Α	
				*		a3,a2	Α	a1,a0	W	Α	Р

The Fast Program Download command introduces a data transfer via the parallel port. $\mathbf{n} = \text{n2,n1,n0}$ denotes the number of 20-bit data words to be transferred, $\mathbf{a} = \text{a3,a2,a1,a0}$ gives the start address. The data must be organized in two times five nibbles to get two words of 20-bit length. If the number n of 20-bit data words is odd, the very last word has to be padded with one additional nibble.

The download must be initiated in the following order:

- Issue Freeze command
- Stop all DMA-transfers
- Issue Fast Program Download command
- Download code via PIO-interface
- Switch appropriate memory area to act as program RAM (register ED_{hex})

 Issue a Run command to start program execution at entry point of downloaded code

Example for *Fast Program Download* command: Download 5 words starting at D0:800, then download 4 words starting at D1:200:

<dw< th=""><th>68</th><th>00</th><th>00:</th><th>></th><th>Freeze</th></dw<>	68	00	00:	>	Freeze
<dw< th=""><th>68</th><th>b3</th><th>b0</th><th>03</th><th>18>Stop all internal transfers</th></dw<>	68	b3	b0	03	18>Stop all internal transfers
<DW	68	b4	30	03	00>
<DW	68	b4	b0	00	00>
<DW	68	b5	30	03	18>
<DW	68	b6	b0	00	00>
<DW	68	bb	b0	03	18>
<DW	68	bс	30	03	00>
<DW	68	b0	60	00	00>
<dw< th=""><th>68 08</th><th>60 00:</th><th>• •</th><th></th><th>initiate download of 5 words start at address D0:800</th></dw<>	68 08	60 00:	• •		initiate download of 5 words start at address D0:800

Now transfer 5 20-bit words via the parallel PIO-port:

d4,d3	d2,d1	d0,d4	d3,d2	d1,d0
d4,d3	d2,d1	d0,d4	d3,d2	d1,d0
d4,d3	d2,d1	d0,x		
<dw 68<="" th=""><th>60 05 00></th><th></th><th></th><th>vnload of 4 words dress D1:200</th></dw>	60 05 00>			vnload of 4 words dress D1:200

Now transfer 4 20-bit words via the parallel PIO-port:

```
d4,d3 d2,d1 d0,d4 d3,d2 d1,d0 d4,d3 d2,d1 d0,d4 d3,d2 d1,d0

<DW 68 b6 bc 00 00>switch the memory area D0:800 ... D0:fff from data to program usage

<DW 68 10 0a> start program execution at address D0:100a
```

3.3.2.11.Serial Program Download

Program downloads may also be performed via the I²C-interface by using the *Write D0/D1 Memory* commands. A similar command sequence as in the Fast Program Download (*Freeze*, stop transfers...) applies.

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3.3.2.12.Read IC Version (Code 7_{hex})

1) send command DW W A data_write A **7**,0 Α 0,0 WAP 2) get version information W A data_read A DW s DR w A n3,n2 Α n1,n0 W Α d3,d2 Α d1,d0 W N Р

With this command the version of the IC is read in two 16 bit words. The first word $\mathbf{n} = n3,n2,n1,n0$ contains the IC's major number (one nibble for each digit). The second word ($\mathbf{d} = d3,d2,d1,d0$) returns the version as shown in Table 3–6.

Table 3-6: Second word of version information

Bit	Nibble	Content
15:12	d3	IC family derivate
11:8	d2	Coded character of order version (add 41 _{hex} to the content of d2 to get ASCII)
7:0	d1,d0	Digit of order version

Example:

Read the version information for MAS 35x9F, derivate 0, order version B2:

<dw 00<="" 68="" 70="" th=""><th>send version command</th></dw>	send version command
<dw 69="" <dr<="" th=""><th>and read</th></dw>	and read
35 09	MAS 3509F
01 02 >	derivate 0, version B2
	(see Section 2.2. on page 8)

0 1	0 2	(hex)
0		Derivate (0F)
1		Version character (0 = "A",, F = "P")
	0 2	Version number (01FF)

3.3.3. List of DSP Registers

The PSelect_Shadow register in Table 3–7 is used to switch four RAM areas from data to program usage and thus enabling the DSP's program counter to access downloaded program code stored at these locations. For normal operation (firmware in ROM), this register must be kept to zero.

Note: DSP registers not given in Table 3–7 must not be written.

3.3.4. List of DSP Memory Cells

Among the user interface control memory cells there are some which have a global meaning and some which control application specific parts of the DSP core. In Table 3–8 and Table 3–9, this is reflected by the key words All, MPEG, and G.729.

Table 3-7: Program Download registers

Address (hex)	R/W	Function	Mode	Default (hex)	Name
6B	R/W	Configuration of Variable RAM Areas	Download	0000	PSelect_Shadow
		Affected RAM area bit[19] D0:800 D0:BFF bit[18] D0:C00 D0:FFF bit[17] D1:800 D1:BFF bit[16] D1:C00 D1:FFF For details of program code download please Section 3.3.2.10. on page 29.	e refer to		

3.3.4.1. Application Selection and Application Running

The AppSelect cell is a global user interface configuration cell, which has to be written in order to start a specific application.

The AppRunning cell is a global user interface status cell, which indicates, which application loop is actually running.

- 1. Write "0" to AppSelect
- 2. Check AppRunning for "0"
- 3. Write value to AppSelect according to Table 3–8 (determines start time of Application program)
- 4. Apply necessary/wanted control settings (D0:346..357)

3.3.4.2. Application Specific Control

The configuration of the MPEG Layer 2/3, AAC decoding and the G.729 codec firmware is done via the control memory cells described in Table 3–9. The changes applied to any of the control memory cells have to be validated by setting bit[0] of memory cell Main I/O Control. This bit will be reset automatically after the changes have been taken over by the DSP.

The status memory cells in Table 3–11 are used to read the decoder status and to get additional MPEG bitstream information.

Note: DSP memory cells not given in Table 3–8 or Table 3–9 must not be written.

Table 3-8: D0 control memory cells: mode selection

Memory Address (hex)	Function	Name
D0:34b	Application Selection All	AppSelect
	AppSelect is used for selecting an application. This is done by setting the appropriate bit to one. It is principally allowed to set more than one bit to one, e.g. setting AppSelect to 1C _{hex} will select all MPEG audio decoders. The auto-detection feature will automatically detect the Layer 2, Layer 3, or AAC data. Setting bit[0] or bit[1] will make the DSP loop in the OS loop or the Top Level loop respectively.	
	To add/remove MPEG layers while running in MPEG decoding mode (e.g. change from Layer 2, Layer 3 (0C $_{\rm hex}$) to Layer 2, Layer 3, AAC (1C $_{\rm hex}$)), the application selection has to be reset to 00 $_{\rm hex}$ before writing the new value.	
	bit[5] G.729 Codec bit[4] MPEG AAC Decoder bit[3] MPEG Layer 3 Decoder bit[2] MPEG Layer 2 Decoder bit[1] Top Level bit[0] Operating System	
D0:34c	Application Running All	AppRunning
	The AppRunning cell is a global user interface status cell, that indicates which application loop is actually running. Prior to writing any of the configuration registers or memory cells (except AppSelect), it has to be checked whether the appropriate bit(s) in the AppRunning cell is set.	
	bit[5] G.729 Codec bit[4] MPEG AAC Decoder bit[3] MPEG Layer 3 Decoder bit[2] MPEG Layer 2 Decoder bit[1] Top Level bit[0] Operating System	

Table 3-9: D0 control memory cells

Memory Address (hex)	Function				Name
D0:346	Main I/O C	ontrol (reset	= 8025 _{hex})	MPEG	IOControlMain
	interface ar mode the c	nd for setting coded audio d ace SDIB (de	or selecting/deselecting the appropriate data up the serial data output interface. In serial i ata (Layer 2, Layer 3, AAC) is expected at the fault). In the 8-bit-parallel input mode the PIC	nput ne serial	
	bit[15]	0: MP3 bloc	input selection ck input mode OFF ck input mode ON		
	bit[14]	Invert seria 0 (reset) 1	output clock (SOC) do not invert SOC invert SOC		
	bit[13:12]	Reserved, ı	must be set to zero		
	bit[11]	Serial data 0 (reset) 1	output delay no additional delay (reset) additional delay of data related to word stro	obe	
	bit[10]	Reserved, ı	must be set to zero		
	bit[9:8]	Input Selec 00 (reset) 01 10 11			
	bit[7:6]	Reserved, ı	must be set to zero		
	bit[5]	SDO Word 0 1 (reset)	Strobe Invert do not invert invert outgoing word strobe signal		
	bit[4]	Bits per Sar 0 (reset) 1	mple at SDO 32 bits/sample 16 bits/sample		
	bit[3]	Reserved, ı	must be set to zero		
	bit[2]	Serial data 0 1 (reset)	input interface B clock invert (pin SIBC) not inverted (data latched at rising clock ed incoming clock signal is inverted (data latch falling clock edge)		
	bit[1]	0 (reset) 1	DEMAND MODE (PLL off, MAS 35x9F is of master) BROADCAST MODE (PLL on, clock of MA locks on data stream)		
	bit[0]	Validate 0 (reset) 1	no forced evaluation of control memory cel changes in control memory will become eff		
	should set t	et after the D	SP has recognized the changes. The control e other D0 control memory cells have been i	ller	

Table 3-9: D0 control memory cells, continued

Memory Address (hex)	Function				Name
D0:347	Interface	InterfaceControl			
	the clock		o enable/disable the data I/O interfaces. In a ata interface interfaces, S/PDIF and SDO, cde.		
	bit[6]	S/PDIF inp 0 (reset) 1	ut selection (used for download modules) select S/PDIF input 1 select S/PDIF input 2		
	bit[5]	Enable/disa 0 (reset) 1	able S/PDIF output enable S/PDIF output S/PDIF output (invalid)		
	bit[4]	Reserved,	must be set to zero		
	bit[3]	Enable/disa 0 (reset) 1	able serial data output SDO SDO valid data SDO invalid data		
	bit[2]	Output cloc 0 1 (reset)	ck characteristic (SDO and S/PDIF outputs) low impedance high impedance		
	bit[1]	reserved, n	nust be set to zero		
	bit[0]	Enable/Dis 0 1 (reset)	able SDI ¹⁾ enable disable		
	Both digital decoded a				
	Changes D0:346 _{hex}	of			
D0:348	Oscillato	r Frequency (reset = 18432 _{dec})	All	OfreqControl
	bit[19:0]	oscillator fr	equency in kHz		
	In order to inal crysta				
	Changes at this memory address must be validated by setting bit[0] of D0:346 _{hex} .				

Table 3-9: D0 control memory cells, continued

Memory Address (hex)	Function		Name		
D0:349	Output Clo	ock Configuration (affects pin CLKO) (reset = 80000 _{hex}) All	OutClkConfig		
	bit[19]	CLKO configuration 0 output clock signal at CLKO 1 (reset) CLKO is tristate			
	The CLKO	output pin of the MAS 35x9F can be disabled via bit[19].			
	bit[18]	Reserved, must be set to zero			
	bit[17]	Additional division by 2 if scaler is on (bit[8] cleared) 0 (reset) oversampling factor 512/768 1 oversampling factor 256/384			
	bit[16:9]				
	bit[8]	Output clock scaler 0 (reset) set output clock according to audio sample rate (see Table 2–1) 1 output clock fixed at 24.576 or 22.5792 MHz			
	For a list of output frequencies at pin CLKO please refer to Table 2-1.				
	bit[7:0]				
	Changes at D0:346.	t this memory address must be validated by setting bit[0] of			
D0:350	Soft Mute	MPEG	SoftMute		
	%0 (reset) %1	mute off mute on			
D0:351	S/PDIF cha	annel status bits category code setting (reset = 8200 _{hex}) All	SpdOutBits		

Table 3-9: D0 control memory cells, continued

Memory Address (hex)	Function				Name
D0:34d	Operation Mode Selection (reset = 0 _{hex}) G.729				UserControl
	The regist	er is used to	switch between basic G.729 operation mod	es.	
	bit[19:7]	Reserved,	set to 0		
	bit[6]	Page head 0 1	ders enable disable		
	If the page 50 data fra Please (se	ch page of a frames.			
	bit[5:4]	Decoding : 00 01 10 11	speed 8 kHz (normal) 6 kHz (slow) 12 kHz (fast) not allowed		
	The record decoding t				
	bit[3]				
	bit[2]	Pause end 0 1	coder/decoder normal operation pause		
	If the paus ished and bit is clear				
	bit[1:0]	Mode 00 01 10 11	idle decode not allowed encode		
	50 frames the UserC	3 _{hex} . Then eated until is enabled, in Fig. 3–4			
	To switch to decoding with speed it me PIO interfaction decoded. It transmission each page				
	To switch of the end of the				

Table 3-9: D0 control memory cells, continued

Memory Address (hex)	Function			Name
D0:34e	I ² S Audio Input/Output Interface (reset = 60 _{hex}) G.729		SDISDOConfig	
	bit[19:15]	Reserved, set to 0		
	bit[14]	Output clock signal 0 standard signal 1 inverted signal		
	bit[13]	Reserved, set to 0		
	bit[12]	Additional delay of input data related to word strobe 0 no delay 1 bit delay		
	bit[11]	Additional delay of output data related to word strobe 0 no delay 1 bit delay		
	bit[10:7]	Reserveded, set to 0		
	bit[6]	Input word strobe signal 0 standard signal 1 inverted signal		
	bit[5]	Output word strobe signal 0 standard signal 1 inverted signal		
	bit[4]	Wordlength 0 32 bits/sample 1 16 bits/sample		
	This setting affects the wordlength on the SDI and SDO interfaces.			
	bit[3]	Input clock signal 0 standard signal 1 inverted signal		
	bit[2:0]	Reserved, set to 0		
	Changes become effective when the codec is started or the mode is changed by writing to the UserControl memory cell.			

Table 3-9: D0 control memory cells, continued

Memory Address (hex)	Function				Name			
D0:34f	Interface S	Status Control (reset =	: 25 _{hex})	G.729	g729_InterfaceCont			
	This contro	ol cell is used to enable	disable interfaces in G.729 mode	Э.	rol			
	bit[6],[4]	reserved, must be se						
	bit [5]	reserved, must be se	reserved, must be set to one					
	bit[3]	0 (reset) SDO val	Enable/disable serial data output SDO 0 (reset) SDO valid data 1 SDO invalid data					
	bit[2]	Output clock characte 0 low impe 1 (reset) high imp						
	bit[1]	reserved, must be se	t to zero					
	bit[0]	Enable/Disable SDI ¹⁾ 0 enable 1 (reset) disable						
D0:352	Volume in	put control: left gain	(reset=80000 _{hex})	G.729	in_L			
D0:353	Volume in	put control: right gain	(reset=0 _{hex})	G.729	in_R			
D0:354	Volume ou	itput control: left $ ightarrow$ le	eft gain (reset=80000 _{hex})	All	out_LL			
D0:355	Volume ou	ıtput control: left → ri	ght gain (reset=0 _{hex})	All	out_LR			
D0:356	Volume ou	itput control: right $ ightarrow$	left gain(reset=0 _{hex})	All	out_RL			
D0:357	Volume co	ontrol: right $ ightarrow$ right ga	ain (reset=80000 _{hex})	All	out_RR			
1) Note: Th	ne pins SIC, S	SII, SID are switched to	output mode, if bit [0] = 1 (Reset	value).				

Table 3-10: MP3 block input mode user interface (all addresses in hex notation)

Addr.	Name	Description
D0:346	IOControlMain	bit[15] MP3 block input select 0: MP3 block input mode OFF 1: MP3 block input mode ON works for input at serial input interface B (bit[9:8] of IOControlMain = 00 _{bin})
		Reset value is 0x8024 (see Table 3–2).
R0:68	MP3BlockConfig	bit[17] data end bit Disables resync timeout. Should be set by the controller at the end of an input file (file end, stop, or pause) when the last requested data block has been fully sent. 0: resync timeout enabled 1: resync timeout disable ↔ no wait for end of block
		bit[16] reserved, set to "0"
		bit[15] start data request 0: MP3 decoder does not send data requests (wait loop) 1: MP3 decoder in operational mode, new input data will be requested via pulses at the demand pin.
		bit[14:0] input block size specific value, do not modify
		Reset value is 0x6670. To set the start bit, the controller must write 0xe670.
R0:7e	PulseDelayCounter	bit[13:0] determines the variable fraction of the demand pulse length. pulseLenVar[ns] = value * 88.58.
D0:34e	ResyncTimeout	bit[19:0] timeout after resync: timeout[µs] = value * 3.32. The default value is 2 ¹⁹ -1, which results in a timeout of 1.74 seconds. For an optimized resync behavior, it is recommended to set this value to zero.
R0:5b	SerialInConfig	bit[14:0] configuration of the serial input interface
D0:350	SoftMute	bit[0] MP3 soft mute 0: audio output on 1: audio output soft muted

Table 3-11: D0 status memory cells

Memory Address	Function		Name
D0:FCF	AAC bitrat	te in bit/s	AACbitrate
D0:FD0	MPEG Fra	me Counter	MPEGFrameCount
	bit[19:0]	number of MPEG frames after synchronization	
	an invalid N	er will be incremented with every new frame that is decoded. With MPEG bit stream at its input (e.g. an invalid header is detected), the F resets the MPEGFrameCount to '0'.	
D0:FD1	MPEG Hea	ader and Status Information	MPEGStatus1
	bit[15]	reserved, must be set to zero	
	bit[14:13]	MPEG ID, Bits 12, 11 of the MPEG header 00	
	bit[12:11]	Bits 14 and 13 of the MPEG header 00 AAC 01 Layer 3 10 Layer 2 11 Layer 1	
	bit[10]	CRC Protection 0 bitstream protected by CRC 1 bitstream not protected by CRC	
	bit[9:2]	Reserved	
	bit[1]	CRC error no CRC error CRC error	
	bit[0]		
	This location tus bits. It was from the bits		

Table 3-11: D0 status memory cells, continued

Memory Address	Function					Name
D0:FD2	MPEG Hea	ader Informat	tion			MPEGStatus2
	bit[15:12]	MPEG Laye	er 2/3 Bitrate			
			MPEG1, L2	MPEG1, L3	MPEG2+2.5, L2/3	
		0000 0001 0010 0011 0100 0101 0110 0111 1000 1001 1010 1011 1100 1101 1110	free 32 48 56 64 80 96 112 128 160 192 224 256 320 384 forbidden	free 32 40 48 56 64 80 96 112 128 160 192 224 256 320 forbidden	free 8 16 24 32 40 48 56 64 80 96 112 128 144 160 forbidden	
	bit[13:10]		equency for MF	PEG2-AAC in Hz		

Table 3-11: D0 status memory cells, continued

Memory Address	Function					Name			
D0:FD2	MPEG Hea	ader Informa	ition, contin	ued		MPEGStatus2			
(continued)	bit[11:10]	Sampling f	requencies ir	n Hz					
			MPEG1	MPEG2	MPEG2.5				
		00 01 10 11	44100 48000 32000 reserved	22050 24000 16000 reserved	11025 12000 8000 reserved				
	bit[9]	Padding B	it						
	bit[8]	reserved							
	bit[7:6]	Mode 00 01 10 11	stereo joint_stere dual chanr single chai	nel	tereo / m/s stereo)				
	bit[5:4]	Mode exte	nsion (applie						
		00 01 10 11	intensity st off on off on	tereo	m/s stereo off off on on				
	bit[3]	Copyright 0/1	Protect Bit	ght protected	/copyright protected				
	bit[2]	Copy/Origi 0/1	Copy/Original Bit 0/1 bitstream is a copy/bitstream is an original						
	bit[1:0]	Emphasis, 00 01 10 11	indicates the none 50/15 μs reserved CCITT J.1						
		ory cell conta er synchroniz			PEG header. It will be set				
	Note that for AAC four bits are needed to define the sampling frequency while for Layer2/Layer3 two bits are sufficient. This leads to an inconsistency in the format of bits 1310.								
D0:FD3	MPEG CR	C Error Cou	nter			CRCErrorCount			
	The counte stream. It v								
D0:FD4		f Bits in And	NumberOfAncillary- Bits						
D0:FD5		Number of valid ancillary bits in the current MPEG frame. Ancillary Data							
	_	on 3.3.6. on p		AncillaryData					
D0:FF1	(550 500110	0.0.0. 0.1 p							

3.3.5. Ancillary Data

The memory fields D0:FD5...D0:ff1 contain the ancillary data. It is organized in 28 words of 16 bit each. The last ancillary bit of a frame is placed at bit 0 in D0:FD5. The position of the first ancillary data bit received can be located via the content of NumberOfAncillaryBits because

int[(NumberOfAncillaryBits-1)/16] + 1 of memory words are used.

Example:

First get the content of 'NumberOfAncillaryBits'

```
<DW 68 c4 00 00 01 0f d4> <DW 69 <DR dd dd>
```

Assume that the MAS 35x9F has received 19 ancillary data bits. Therefore, it is necessary to read two 16-bit words:

```
<DW 68 c4 00 Short Read from D0 00 02 0f d5> read 2 words starting at D0:fd5 <DW 69 <DR dd dd dd dd> receive the 2 16-bit words
```

The first bit received from the MPEG source is at position 2 of D0:FD6; the last bit received is at the LSB of D0:fd5.

Table 3-12: Content of D0:fd5 after reception of 19 ancillary bits.

D0:fd5	MSB	14	13	12	11	10	9	8	7	6	5	4	3	2	1	LSB
Ancillary Data	4th bit	5th bit	6th bit											17th bit	18th bit	last bit

Table 3–13: Content of D0:fd6 after reception of 19 ancillary bits.

D0:fd6	MSB	14	13	12	11	10	9	8	7	6	5	4	3	2	1	LSB
Ancillary Data	х	х	х	х	х	х	х	х	х	х	х	х	x	first bit	2nd bit	3rd bit

3.3.6. Reading of the Memory Cells "Number of Bits in Ancillary Data" and "Ancillary Data"

When in Broadcast Mode, reading of the cells "Number of Bits in Ancillary Data" and "Ancillary Data" will lead to unpredictable results. These cells are described in Table 3–11 on page 43.

The same applies to the "Number of Bits in Ancillary Data" and "Ancillary Data" of the preliminary data sheet MAS 3587F.

3.3.7. DSP Volume Control

The digital baseband volume matrix is used for controlling the digital gain as shown in Fig. 3–3. This volume control is effective on both, the digital audio output and the data stream to the D/A converters. The values are in 20-bit 2's complement notation.

Table 3–14 shows the proposed settings for the 4 volume matrix coefficients for stereo, left and right mono. The gain factors are given in fixed point notation $(-1.0 \times 2^{19} = 80000_{hex})$.

If channels are mixed, care must be taken to prevent clipping at high amplitudes. Therefore, the sum of the absolute values of coefficients for one output channel must be less than 1.0.

For normal operating conditions it is recommended to use the main volume control of the audio codec instead (register 00 10_{hex} of the audio codec).

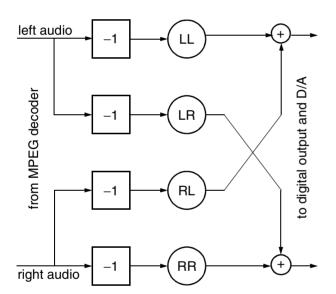


Fig. 3–3: Digital volume matrix

Table 3–14: Settings for the digital volume matrix

Memory	D0:354	D0:355	D0:356	D0:357
Name	LL	LR	RL	RR
Stereo (default)	-1.0	0	0	-1.0
Mono left	-1.0	-1.0	0	0
Mono right	0	0	-1.0	-1.0

3.3.8. Explanation of the G.729A Data Format

The codec is working on a page basis where the encoding and decoding is performed in blocks of 50 G.729 frames, whereas each frame consists of 10 bytes in byte-swapped order (see Fig. 3–4). Therefore most changes to the UserControl register become effective when processing of the current page is finished. The pages are optionally preceded by 10 byte header frames (see Table 3–15).

Table 3-15: Content of page header

Byte	1	2	3	4	5	6	7	8	9	10
Value (hex)	64	6d	72	31	64	61	74	61	F4	01

Switching directly from encoding to decoding mode (or vice versa) is not allowed. Instead, the controller has to send a stop request to the MAS 35x9F (writing 0_{hex} to UserControl) and must keep on sending data in decoding mode or receive data in encoding mode until the current page of 50 frames is finished. After this run-out time, the encoding or decoding can be started again.

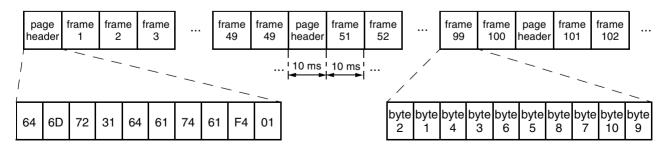


Fig. 3-4: Schematic timing of the data transmission with preceeding header

3.4. Audio Codec Access Protocol

The MAS 35x9F has 16-bit wide registers for the control of the audio codec. These registers are accessed via the I^2C subaddresses codec_write (6Chex) and codec_read (6Dhex).

3.4.1. Write Codec Register

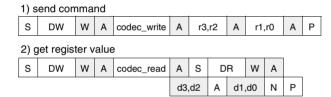


The controller writes the 16-bit value ($\mathbf{d} = d3,d2,d1,d0$) into the MAS 35x9F codec register ($\mathbf{r} = r3,r2,r1,r0$). A list of registers is given in Table 3–16.

Example: Writing the value 1234_{hex} into the codec register with the number 00 $1B_{hex}$:

<DW 6c 00 1b 12 34>

3.4.2. Read Codec Register



Reading the codec registers also needs a set-up for the register address and an additional start condition during the actual read cycle. A list of status registers is given in Table 3–17.

3.4.3. Codec Registers

Table 3–16: Codec control registers on I²C subaddress 6C_{hex}

Register Address (hex)	Function		Name
CONVERT	ER CONFIG	URATION	
00 00	Audio Cod	dec Configuration	CONV_CONF
		ated to the D/A full-scale output voltage er to (see Section 4.6.3. on page 81).	
	bit[15:12]	A/D converter left amplifier gain = n*1.5-3 [dB]	
	bit[11:8]	A/D converter right amplifier gain = n*1.5–3 [dB] 1111 +19.5 dB 1110 +18.0 dB	
		0011 +1.5 dB 0010 0.0 dB 0001 -1.5 dB 0000 - 3.0 dB	
	bit[7:4]	Microphone amplifier gain = $n*1.5+21$ [dB] 1111 +43.5 dB 1110 +42.0 dB	
		 0001 +22.5 dB 0000 +21.0 dB	
	bit[3]	Input selection for left A/D converter channel O line-in 1 microphone	
	bit[2]	Enable left A/D converter ¹⁾	
	bit[1]	Enable right A/D converter ¹⁾	
	bit[0]	Enable D/A converter ¹⁾	

¹⁾ The generation of the internal DC reference voltage for the D/A converter is also controlled with this bit. In order to avoid click noise, the reference voltage at pin AGNDC should have reached a near ground potential before repowering the D/A converter after a short down phase.

Alternatively, at least one of the A/D converters (bits[2] or [1]) should remain set during short power-down phases of the D/A. Then the DC reference voltage generation for the D/A converter will not be interrupted.

Table 3–16: Codec control registers on I²C subaddress 6C_{hex}, continued

Register Address (hex)	Function			Name	
INPUT MO	DE SELECT	Ţ			
00 08	Input Mod	le Setting		ADC_IN_MODE	
	bit[15]		stereo input mode left channel is copied into the right channel		
	bit[14:2]	Reserved, m	Reserved, must be set to 0		
	bit[1:0]	1	select deemphasis off deemphasis 50 µs deemphasis 75 µs		
OUTPUT N	MODE SELE	СТ			
	D/A Conv	erter Source M	lixer		
00 06	MIX ADC	scale		DAC_IN_ADC	
00 07	MIX DSP	scale		DAC_IN_DSP	
	bit[15:8]	0 20 40	g factor (hex) off 50 % (–6 dB gain) 100 % (0 dB gain) 200 % (+6 dB gain)		
		of both mixing audio process	inputs exceeds 100 %, clipping may occur in the sing.		
00 0E	D/A Conv	erter Output M	lode	DAC_OUT_MODE	
	bit[15]		stereo through mono matrix applied		
	bit[14]	Invert right cl 0 1			
	bit[1:0]	Reserved, m	uust be set to 0		
		e between pins	output power a single loudspeaker can be connected OUTL and OUTR. In this mode bit[15] and bit[14]		

Table 3–16: Codec control registers on I²C subaddress 6C_{hex}, continued

Register Address (hex)	Function	Name
BASEBA	ND FEATURES	
00 14	Bass	BASS
	$\begin{array}{lll} bit[15:8] & Bass\ range \\ & 60_{hex} & +12\ dB \\ & 58_{hex} & +11\ dB \\ & \\ & 08_{hex} & +1\ dB \\ & 00_{hex} & 0\ dB \\ & F8_{hex} & -1\ dB \\ & \\ & A8_{hex} & -11\ dB \\ & A0_{hex} & -12\ dB \\ \end{array}$ Higher resolution is possible, one LSB step results in a gain step of about 1/8 dB. With positive bass settings clipping of the output signal may occur. Therefore, it is not recommended to set bass to a value that, in conjunction with volume, would result in an overall positive gain. The settings require: max (bass, treble) + loudness + volume $\leq 0\ dB$ bit[7:0] Not used, must be set to 0	
00 15	Treble bit[15:8] Treble range 60 _{hex} +12 dB 58 _{hex} +11 dB 08 _{hex} +1 dB 00 _{hex} 0 dB F8 _{hex} -1 dB A8 _{hex} -11 dB A0 _{hex} -12 dB Higher resolution is possible, one LSB step results in a gain step of about 1/8 dB. With positive treble settings, clipping of the output signal may occur. Therefore, it is not recommended to set treble to a value that, in conjunction with loudness and volume, would result in an overall positive gain. The settings require: max (bass, treble) + loudness + volume ≤ 0 dB bit[7:0] Not used, must be set to 0	TREBLE

Table 3–16: Codec control registers on I²C subaddress 6C_{hex}, continued

Register Address (hex)	Function	Function					
00 1E	Loudnes	ss		LDNESS			
	bit[15:8]	Loudnes 44 _{hex} 40 _{hex}	s Gain +17 dB +16 dB				
		04 _{hex} 00 _{hex}	+1 dB 0 dB				
	bit[7:0]	Loudnes 00 _{hex} 04 _{hex}					
	Higher re step of al						
	keeping t intended Because	the amplitu loudness h loudness ii	the volume of low- and high-frequency signals, while de of the 1-kHz reference frequency constant. The has to be set according to the actual volume setting. Introduces gain, it is not recommended to set loudness to a action with volume, would result in an overall positive gain.				
	The setti						
	The corner frequency for bass amplification can be set to two different values. In Super Bass mode, the corner frequency is shifted up. The point of constant volume is shifted from 1 kHz to 2 kHz.						

Table 3–16: Codec control registers on I²C subaddress 6C_{hex}, continued

Register Address (hex)	Function			Name
Micronas I	Bass (MB)			
00 22	MB Effect	Strength		MB_STR
	bit[15:8]	00 _{hex} 7F _{hex}	MB off (default) maximum MB	
		fect strength dium MB effe	can be adjusted in 1dB steps. A value of 40 _{hex} will ect.	
00 23	MB Harmo	onics		MB_HAR
	bit[15:8]	00 _{hex} 64 _{hex} 7F _{hex}	no harmonics are added (default) 50% fundamentals + 50% harmonics 100% harmonics	
	The MB ex by creating bandpass that are be of the harm			
00 24	MB Center Frequency			MB_FC
	bit[15:8]	2 3	20 Hz 30 Hz	
		30	300 Hz	
	filter (see F match the	Fig. 3–5 on pocutoff freque	ncy defines the center frequency of the MB bandpass age 51). The center frequency should approximately ncy of the loudspeakers. For high end loudspeakers, d 50 Hz, for low end speakers around 90 Hz	
00 21	MB Shape			MB_SHAPE
	bit[15:8]	530	corner frequency in 10-Hz steps (range: 50300 Hz)	
	pass can b quency of (MB_FC) r	e increased this filter clos esults in a na	filter the steepness of the falling edge of the MB band-(see Fig. 3–5 on page 51). Choosing the corner frese to the center frequency of the bandpass filter arrow MB frequency range. The smaller this range, the s. The recommended value is around $1.5 \times MB_FC$	
	MB Switch	า		MB_SWITCH
	bit[7:2]		reserved, must be set to zero	
	bit[1]	0 1	MB switch MB off MB on	

Table 3–16: Codec control registers on I²C subaddress 6C_{hex}, continued

Register Address (hex)	Function	Name
VOLUME		
00 12	Automatic Volume Correction (AVC) Loudspeaker Channel	AVC
	bit[15:12] 0 _{hex} AVC off (and reset internal variables) 8 _{hex} AVC on	
	bit[11:8] 8 _{hex} 8 s decay time 4 _{hex} 4 s decay time 2 _{hex} 2 s decay time 1 _{hex} 20 ms decay time (intended for quick adaptation to the average volume level after track or source change)	
	Note: To reset the internal variables, the AVC should be switched off and then on again during any track or source change. For standard applications, the recommended decay time is 4 s.	
00 11	Balance	BALANCE
	bit[15:8] Balance range 7F _{hex} left –127 dB, right 0 dB 7E _{hex} left –126 dB, right 0 dB 	
	01 _{hex} left -1 dB, right 0 dB 00 _{hex} left 0 dB, right 0 dB FF _{hex} left 0 dB, right -1 dB	
	81 _{hex} left 0 dB, right –127 dB 80 _{hex} left 0 dB, right –128 dB	
	Positive balance settings reduce the left channel without affecting the right channel; negative settings reduce the right channel leaving the left channel unaffected.	
00 10	Volume Control	VOLUME
	bit[15:8] Volume table with 1 dB step size 7F _{hex} +12 dB (maximum volume) 7E _{hex} +11 dB	
	74 _{hex} +1 dB 73 _{hex} 0 dB 72 _{hex} -1 dB	
	02 _{hex} -113 dB 01 _{hex} -114 dB 00 _{hex} mute (reset)	
	bit[7:0] Not used, must be set to 0	
	This main volume control is applied to the analog outputs only. It is split between a digital and an analog function. In order to avoid noise due to large changes of the setting, the actual setting is internally low-pass filtered.	
	With large scale input signals, positive volume settings may lead to signal clipping.	

Table 3-17: Codec status registers on I²C subaddress 6D_{hex}

Register Address (hex)	Function		Name
INPUT QU	ASI-PEAK		
00 0A	A/D Converter Quas	si-Peak Detector Readout Left	QPEAK_L
	bit[14:0] 0000 2000 4000 7FFF	positive 15-bit value, linear scale 0% 25% (–12 dBFS) 50% (–6 dBFS) 100% (0 dBFS)	
00 0B	A/D Converter Quas	QPEAK_R	
	bit[14:0] 0000 2000 4000 7FFF	positive 15-bit value, linear scale 0% 25% (–12 dBFS) 50% (–6 dBFS) 100% (0 dBFS)	
ОИТРИТ (QUASI-PEAK		
00 0C	Audio Processing I	nput Quasi-Peak Detector Readout Left	DQPEAK_L
	bit[14:0]	positive 15-bit value, linear scale	
00 0D	Audio Processing I	nput Quasi-Peak Detector Readout Right	DQPEAK_R
	bit[14:0]	positive 15-bit value, linear scale	

3.4.4. Basic MB Configuration

With the parameters described in Table 3–16, the Micronas Bass system (MB) can be customized to create different bass effects, as well as to fit the MB to various loudspeaker characteristics. The easiest way to find a good set of parameter is by selecting one of the settings below, listening to music with strong bass content and adjusting the MB parameters:

- MB_STR: Increase/decrease the strength of the MB effect
- MB_HAR: Increase/decrease the content of low frequency harmonics
- MB_FC: Shift the MB effect to lower/higher frequencies
- MB_SHAPE: Widen/narrow MB frequency range

(which results in a softer/harder bass sound), turn on/off the MB

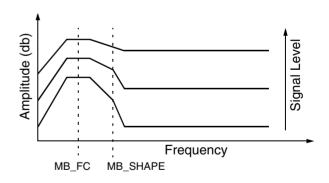


Fig. 3–5: Micronas Bass (MB): Bass boost in relation to input signal level

■ Table 3–18: Suggested MB settings

Function	MB_STR (22 _{hex})	MB_HAR (23 _{hex})	MB_FC (24 _{hex})	MB_SHAPE (21 _{hex})	
MB off	xxxx _{hex}	xxxx _{hex}	xxxx _{hex}	xx00 _{hex}	
Low end headphones, medium effect	5000 _{hex}	3000 _{hex}	0600 _{hex}	0902 _{hex}	

4. Specifications

4.1. Outline Dimensions

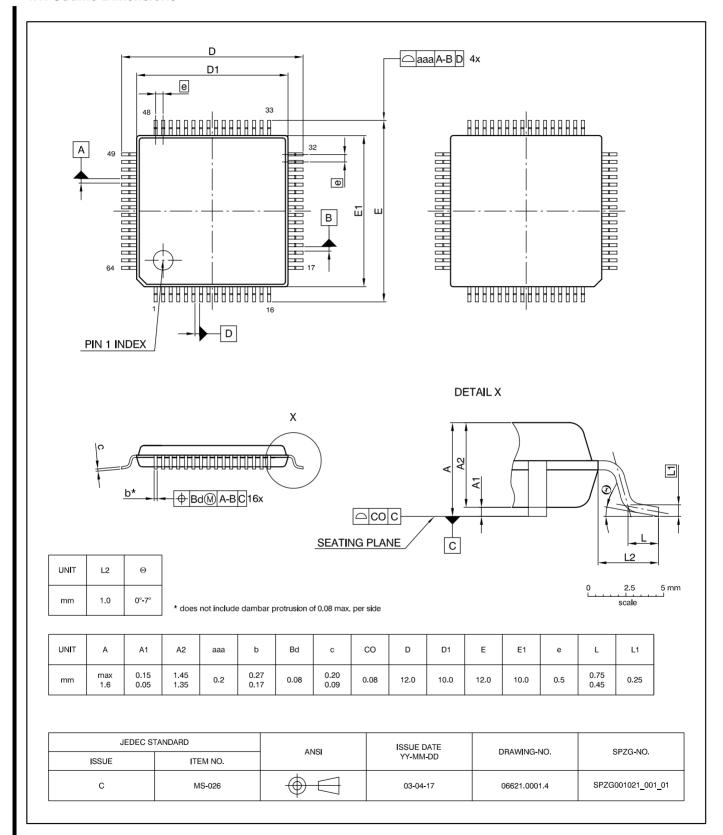


Fig. 4–1:

PLQFP64-1: Plastic Low Quad Flat Package, 64 leads, $10 \times 10 \times 1.4 \text{ mm}^3$

Ordering code: FH

Weight approximately 0.35 g

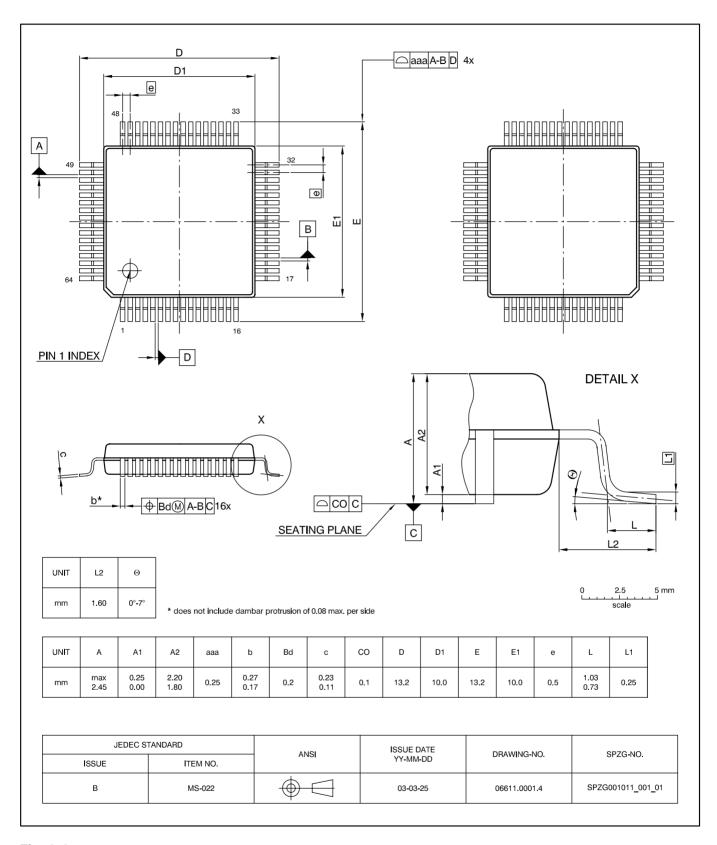


Fig. 4–2: PMQFP64-2: Plastic Metric Quad Flat Package, 64 leads, $10 \times 10 \times 2 \text{ mm}^3$ Ordering code: QI Weight approximately 0.5 g

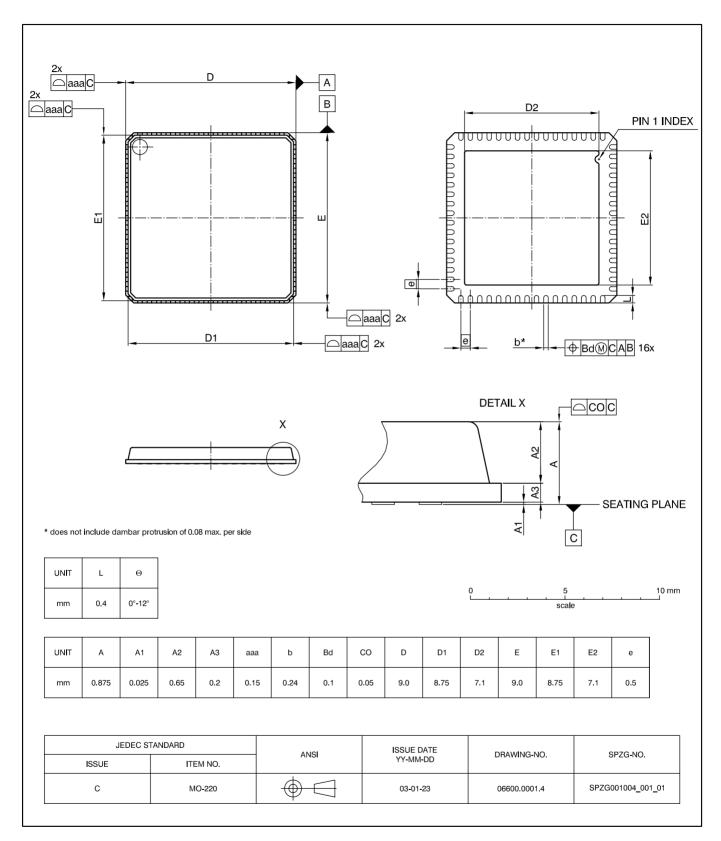


Fig. 4–3: PQFN64-1: Plastic Quad Flat Non-leaded package, 64 pins, $9 \times 9 \times 0.85 \text{ mm}^3$, 0.5 mm pitch Ordering code: XK Weight approximately 0.23 g

4.2. Pin Connections and Short Descriptions

NC = not connected, leave vacant
LV = if not used, leave vacant
S.T.B. = shorted to BAGNDI if not used
DVSS = if not used, connect to DVSS
OBL = obligatory; connect as described in circuit diagram
AHVSS = connect to AHVSS

Pin No.		Pin Name	Туре	Connection	Short Description	
PLQFP 64-1	PMQFP 64-2	PQFN 64-1			(If not used)	
1	1	1	AGNDC		OBL	Analog reference voltage
2	2	2	MICIN	IN	LV	Input for internal micro- phone amplifier
3	3	3	МІСВІ	IN	LV	Bias for internal microphone
4	4	4	INL	IN	LV	Left A/D input
5	5	5	INR	IN	LV	Right A/D input
6	6	6	TE	IN	OBL	Test enable
7	7	7	XTI	IN	OBL	Crystal oscillator (ext. clock) input
8	8	8	хто	OUT	LV	Crystal oscillator output
9	9	9	POR	IN	OBL	Power on reset, active low
10	10	10	VSS	SUPPLY	OBL	DSP supply ground
11	11	11	xvss	SUPPLY	OBL	Digital output supply ground
12	12	12	VDD	SUPPLY	OBL	DSP supply
13	13	13	XVDD	SUPPLY	OBL	Digital output supply
14	14	14	I2CVDD	SUPPLY	OBL	I ² C supply
15	15	15	DVS	IN	OBL	I ² C device address selector
16	16	16	VSENS1	IN/OUT	VDD	Sense input and power output of DC/DC 1 converter
17	17	17	DCSO1	SUPPLY	LV	DC/DC 1 switch output
18	18	18	DCSG1	SUPPLY	VSS	DC/DC 1 switch ground
19	19	19	DCSG2	SUPPLY	VSS	DC/DC 2 switch ground
20	20	20	DCSO2	SUPPLY	LV	DC/DC 2 switch output
21	21	21	VSENS2	IN/OUT	VDD	Sense input and power output of DC/DC 2 converter
22	22	22	DCEN	IN	VSS	DC/DC enable (both converters)

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PLQFP 64-1	Pin No. PMQFP 64-2	PQFN 64-1	Pin Name	Туре	Connection (If not used)	Short Description
23	23	23	CLKO	OUT	LV	Clock output
24	24	24	I2CC	IN/OUT	OBL	I ² C clock
25	25	25	I2CD	IN/OUT	OBL	I ² C data
26	26	26	SYNC	OUT	LV	Sync output
27	27	27	VBAT	IN	LV	Battery voltage monitor input
28	28	28	PUP	OUT	LV	DC Converters Power-Up Signal
29	29	29	EOD	OUT	LV	PIO end of DMA, active low
30	30	30	PRTR	OUT	LV	PIO ready to read, active low
31	31	31	PRTW	OUT	LV	PIO ready to write, active low
32	32	32	PR	IN	VDD	PIO DMA request, active high
33	33	33	PCS	IN	VSS	PIO chip select, active low
34	34	34	PI19	IN/OUT	LV	PIO data bit[7] (MSB)
35	35	35	PI18	IN/OUT	LV	PIO data bit[6]
36	36	36	PI17	IN/OUT	LV	PIO data bit[5]
37	37	37	PI16	IN/OUT	LV	PIO data bit[4]
38	38	38	PI15	IN/OUT	LV	PIO data bit[3]
39	39	39	PI14	IN/OUT	LV	PIO data bit[2]
40	40	40	PI13	IN/OUT	LV	PIO data bit[1]
41	41	41	PI12	IN/OUT	LV	PIO data bit[0] (LSB)
42	42	42	SOD	OUT	LV	Serial output data
43	43	43	SOI	OUT	LV	Serial output word identification
44	44	44	soc	OUT	LV	Serial output clock
45	45	45	SID	IN/OUT	OBL	Serial input data, interface A
46	46	46	SII	IN/OUT	OBL	Serial input word identification, interface A
47	47	47	SIC	IN/OUT	OBL	Serial input clock, interface A
48	48	48	SPDO	OUT	LV	S/PDIF output interface
49	49	49	SIBD	IN	VSS	Serial input data, interface B

Pin No.			Pin Name	Туре	Connection	Short Description
PLQFP 64-1	PMQFP 64-2	PQFN 64-1			(If not used)	
50	50	50	SIBC	IN	VSS	Serial input clock, interface B
51	51	51	SIBI	IN	VSS	Serial input word identification, interface B
52	52	52	SPDI2	IN	LV	Active differential S/PDIF input 2
53	53	53	SPDI1	IN	LV	Active differential S/PDIF input 1
54	54	54	SPDIR	IN	LV	Reference differential S/ PDIF input 1 and 2
55	55	55	FILTL	IN	OBL	Feedback input for left amplifier
56	56	56	AVDD0	SUPPLY	OBL	Analog supply for output amplifiers
57	57	57	OUTL	OUT	LV	Left analog output
58	58	58	OUTR	OUT	LV	Right analog output
59	59	59	AVSS0	SUPPLY	OBL	Analog ground for output amplifiers
60	60	60	FILTR	IN	OBL	Feedback for right output amplifier
61	61	61	AVSS1	SUPPLY	OBL	Analog ground
62	62	62	VREF		OBL	Analog reference ground
63	63	63	PVDD	SUPPLY	OBL	Internal power supply
64	64	64	AVDD1	SUPPLY	OBL	Analog Supply

4.3. Pin Descriptions

4.3.1. Power Supply Pins

The use of all power supply pins is mandatory to achieve correct function of the MAS 35x9F.

VDD, VSS SUPPLY

Digital supply pins.

XVDD, XVSS SUPPLY

Supply for digital output pins.

I2CVDD SUPPLY

Supply for I²C interface circuitry. This net uses VSS or XVSS as the ground return line.

PVDD SUPPLY

Auxiliary pin for analog circuitry. This pin has to be connected via a 3 nF capacitor to AVDD1. Extra care should be taken to achieve a low-inductance PCB line.

AVDD0/AVSS0 SUPPLY

Supply for analog output amplifier.

AVDD1/AVSS1 SUPPLY

Supply for internal analog circuits (A/D, D/A converters, clock, PLL, S/PDIF input).

AVDD0/AVSS0 and AVDD1/AVSS1 should receive the same supply voltages.

4.3.2. Analog Reference Pins

AGNDC

Internal analog reference voltage. This pin serves as the internal ground connection for the analog circuitry.

VREF

Analog reference ground. All analog inputs and outputs should drive their return currents using separate traces to a ground starpoint close to this pin. Connect to AVSS1. This reference pin should be as noise-free as possible.

4.3.3. DC/DC Converters and Battery Voltage Supervision

DCSG1/DCSG2 SUPPLY

DC/DC converters switch ground. Connect using separate wide trace to negative pole of battery cell. Connect also to AVSS0/1 and VSS/XVSS, VREF.

DCSO1/DCSO2 SUPPLY

DC/DC converter switch connection. If the respective DC/DC converter is not used, this pin must be left vacant.

VSENS1/VSENS2

IN

Sense input and power output of DC/DC converters. If the respective DC/DC converter is not used, this pin should be connected to a supply to enable proper function of the PUP-signals.

DCEN IN

Enable signal for both DC/DC converters. If none of the DC/DC converters is used, this pin must be connected to VSS.

PUP OUT

Power-up. This signal is set when the required voltages are available at both DC/DC converter output pins VSENS1 and VSENS2. The signal is cleared when both voltages have dropped below the reset level in the DCCF Register.

VBAT IN

Analog input for battery voltage supervision.

4.3.4. Oscillator Pins and Clocking

XTI IN XTO OUT

The XTI pin is connected to the input of the internal crystal oscillator, the XTO pin to its output. Each pin should be directly connected to the crystal and to a ground-connected capacitor (see application diagram, Fig. 5–1 on page 89).

CLKO OUT

The CLKO can drive an output clock line.

4.3.5. Control Lines

I2CC SCL IN/OUT I2CD SDA IN/OUT

Standard I²C control lines.

DVS

 I^2C device address selector. Connect this pin either to VDD (I^2C device address: $3E/3F_{hex}$) or VSS (I^2C device address: $3C/3D_{hex}$) to select a proper I^2C device address (see also Table 3–2 on page 22).

4.3.6. Parallel Interface Lines

PI12..PI19 IN/OUT

The PIO input pins PI12..PI19 are used as 8-bit I/O interface to a microcontroller in order to transfer compressed and uncompressed data. PI12 is the LSB, PI19 the MSB.

4.3.6.1. PIO Handshake Lines

PCS

The PIO chip select PCS must be set to '0' to activate the PIO in operation mode.

PR IN

Pin PR must be set to '1' to validate data output from MAS 35x9F PIO pins.

PRTR OUT

Ready to read. This signal indicates that the MAS 35x9F is able to receive data in PIO input mode.

PRTW OUT

Ready to write. This pin indicates that MAS 35x9F has data available for PIO output mode.

<u>EOD</u> OUT

EOD indicates the end of an DMA cycle in the IC's PIO input mode. In 'serial' input mode it is used as Demand signal, that indicates that new input data are required.

4.3.7. Serial Input Interface (SDI)

SID	DATA	IN/OUT
SII	WORD STROBE	IN/OUT
SIC	CLOCK	IN/OUT

I²S compatible serial interface A for digital audio data. In the standard firmware this interface is not used. Note: Please refer to Bit [0] of Table 3–5

4.3.8. Serial Input Interface B (SDIB)

SIBD	DATA	IN
SIBI	WORD STROBE	IN
SIBC	CLOCK	IN

The serial interface B is primarily used as bitstream input interface. The SIBI line must be connected to VSS in the standard application.

4.3.9. Serial Output Interface (SDO)

SOD	DATA	OUT
SOI	WORD STROBE	OUT
SOC	CLOCK	IN/OUT

Data, Frame Indication, and Clock line of the serial output interface. The SOI is reconfigurable and can be adapted to several I²S compliant modes.

4.3.10. S/PDIF Input Interface

SPDI1					IN
SPDI2					IN
SPDIR					IN
000154	000150				

SPDIF1 and SPDIF2 are alternative input pins for S/PDIF sources according to the IEC 958 consumer

specification are used in conjunction with download software only. A switch at D0:ff6 selects one of these pins at a time. The SPDIR pin is a common reference for both input lines (see Fig. 5–1 on page 89).

4.3.11. S/PDIF Output Interface

SPDO OUT

The SPDO pin provides an digital output with standard CMOS level that is compliant to the IEC 958 consumer specification.

4.3.12. Analog Input Interfaces

In the standard MPEG-decoding DSP firmware the analog inputs are not used. However, they can be selected as a source for the D/A converters (set MIX ADC scale of the D/A Converter Source Mixer, Register 00 $06_{\rm hex}$ in Table 3–16).

MICIN IN MICBI IN

The MICIN input may be directly used as electret microphone input, which should be connected as described in application information (see Fig. 5–1 on page 89). The MICBI signal provides the supply voltage for these microphones.

INL IN IN IN

INL and INR are analog line-in input lines. They are connected to the embedded stereo A/D converter of the MAS 35x9F. The sources should be AC-coupled. The reference ground for these analog input pins is the VREF pin.

4.3.13. Analog Output Interfaces

OUTL OUT OUT

OUTL and OUTR are left and right analog outputs, that may be directly connected to the headphones as described in the application information (see Fig. 5–1 on page 89).

FILTL IN

Connection to input terminal of output amplifier. Can be used to connect a capacitance from OUTL respectively OUTR to FILTL respectively FILTR in parallel to feedback resistor and thus implement a low pass filter to reduce the out-of-band noise of the DAC.

4.3.14. Miscellaneous

SYNC OUT

The SYNC signal indicates the detection of a frame start in the input data of MAS 35x9F. Usually this signal generates an interrupt in the controller.

POR IN

The Power-On Re<u>set pin</u> is used to reset the whole MAS 35x9F. The POR is an active-low signal (see Fig. 5–1 on page 89).

TE IN

The TE pin is for production test only and must be connected with VSS in all applications.

4.4. Pin Configuration

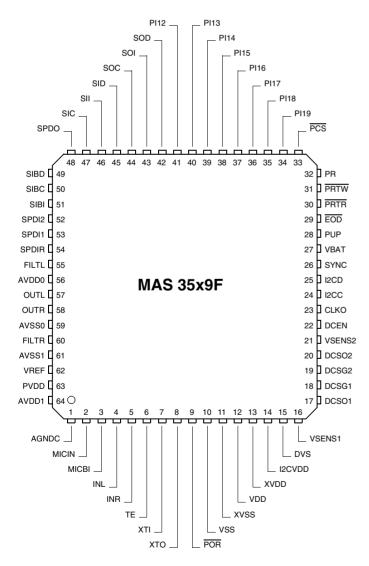


Fig. 4-4: PLQFP64-1/PMQFP64-2 and PQFN64-1 package

4.5. Internal Pin Circuits

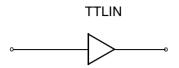


Fig. 4–5: Input pins PCS, PR

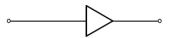


Fig. 4–6: Input pin TE, DVS, POR

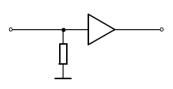


Fig. 4-7: Input pin DCEN

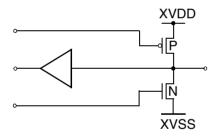


Fig. 4–8: Input/output pins SOC, SOI, SOD, PI12...PI19, SPDO

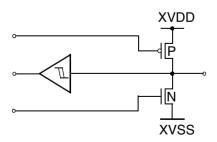


Fig. 4-9: Input pins SIC, SII, SID

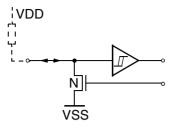


Fig. 4-10: Input/output pins I2CC, I2CD

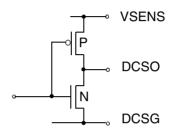


Fig. 4–11: Input/output pins DCSO1/2, DCSG1/2, VSENS1/2

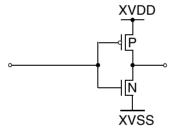


Fig. 4–12: Output pins $\overline{\text{PRTW}}$, $\overline{\text{EOD}}$, $\overline{\text{PRTR}}$, CLKO, SYNC, PUP

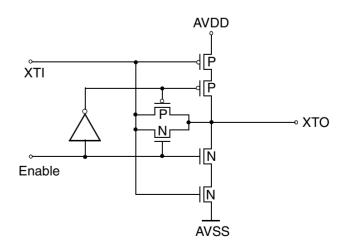


Fig. 4-13: Clock oscillator XTI, XTO

Micronas

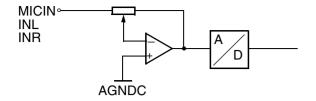


Fig. 4-14: Analog input pins MICIN, INL, INR

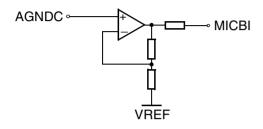


Fig. 4–15: Microphone bias pin (MICBI)

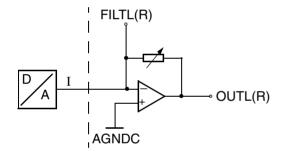


Fig. 4–16: Analog outputs OUTL(R) and connections for filter capacitors FILTL(R)

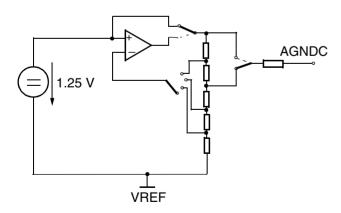


Fig. 4–17: Analog ground generation with pin to connect external capacitor

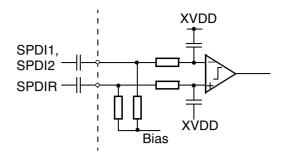


Fig. 4-18: S/PDIF inputs

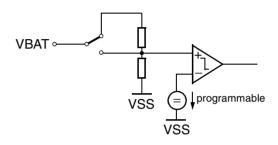


Fig. 4-19: Battery voltage monitor VBAT

4.5.1.Reset Pin Configuration for MAS 3529F and MAS 3539F

The Power-On Reset pin POR is used to reset the entire MAS 35x9F. The POR is an active-low signal.

Note: If a pull-up resistor is used for building a delay time here (see Fig. 5–1 on page 89), referred to the VDD pins, the maximum allowed value for this resistor is 3.3 kOhm!

4.6. Electrical Characteristics

Abbreviations:

tbd = to be defined vacant = not applicable positive current values mean current flowing into the chip

4.6.1. Absolute Maximum Ratings

Stresses beyond those listed in the "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only. Functional operation of the device at these conditions is not implied. Exposure to absolute maximum rating conditions for extended periods will affect device reliability.

This device contains circuitry to protect the inputs and outputs against damage due to high static voltages or electric fields; however, it is advised that normal precautions be taken to avoid application of any voltage higher than absolute maximum-rated voltages to this high-impedance circuit.

All voltages listed are referenced to ground (V_{SUP1} , V_{SUP2} , V_{SUP3} = 0 V) except where noted.

All GND pins must be connected to a low-resistive ground plane close to the IC.

Do not insert the device into a live socket. Instead, apply power by switching on the external power supply. For power up/down sequences, see the instructions in Section 2.6. of this document.

Table 4-1: Absolute Maximum Ratings

Symbol	Parameter	Pin Name	Limit \	/alues	Unit
			Min.	Max.	
T _A	Extended Ambient Temperature		-40	85 ¹⁾	°C
T _C	Case Temperature PLQFP64-1 PMQFP64-2 PQFN64-1			115 110 100	°C
T _S	Storage Temperature		-40	125	°C
P _{MAX}	Maximum Power Dissipation PLQFP64-1 PMQFP64-2 PQFN64-1	VDD, XVDD, AVDD0/1, I2CVDD		2) 0.67 0.98 0.87	W
V _{SUP1}	Supply Voltage 1	VDD, XVDD, I2CVDD, AVDD0/1 ³⁾	-0.3	6	V
V _{SUP2}	Supply Voltage 2	VDD, XVDD, I2CVDD, AVDD0/1 ³⁾	-0.3	6	V

¹⁾ A power-optimized board layout is recommended. The case temperature mentioned in the "Absolute Maximum Ratings" must not be exceeded at worst case conditions of the application.

²⁾ Package limits

³⁾ Both AVDD0 and AVDD1 have to be connected together!

Table 4-1: Absolute Maximum Ratings, continued

Symbol	mbol Parameter Pin Name		Limit \	Unit	
			Min.	Max.	
V _{SUP3}	Supply Voltage 3	VDD, XVDD, I2CVDD, AVDD0/1 ¹⁾	-0.3	6	V
V _{II2C}	Input Voltage, I ² C pins	12CC, 12CD	-0.3	6	V
V _{ID}	Input Voltage	all digital inputs	-0.3	V _{SUP} + 0.3	٧
I _{ID}	Input Current	all digital inputs	-20	+20	mA
V _{IA}	Input Voltage	all analog inputs	-0.3	V _{SUP} + 0.3	٧
I _{IA}	Input Current	all analog inputs	- 5	+5	mA
I _{Oaudio}	Output Current, audio output ²⁾	OUTL/R	-0.2	0.2	Α
l _{Odig}	Output Current, all digital outputs ³⁾		-50	+50	mA
I _{Odcdc1}	Output Current DCDC converter 1	DCSO1		1.5	Α
I _{Odcdc2}	Output Current DCDC converter 2	DCSO2		1.5	Α

¹⁾ Both AVDD0 and AVDD1 have to be connected together!

²⁾ These pins are not short-circuit-proof!

³⁾ Total chip power dissipation must not exceed maximum rating.

4.6.1.1. Recommended Operating Conditions

Functional operation of the device beyond those indicated in the "Recommended Operating Conditions/Characteristics" is not implied and may result in unpredictable behavior, reduce reliability and lifetime of the device.

All voltages listed are referenced to ground (V_{SUP1} , V_{SUP2} , V_{SUP3} = 0 V) except where noted. All GND pins must be connected to a low-resistive ground plane close to the IC.

Do not insert the device into a live socket. Instead, apply power by switching on the external power supply. For power up/down sequences, see the instructions in section Section 2.10.2. of this document.

	Symbol	Parameter	Pin Name	Limit Values		3	Unit
				Min.	Тур.	Max.	
	T _A	Ambient Operating Temperature ¹⁾ PLQFP64-1, PMQFP64-2, PQFN64-1 - Operating Conditions - Extended temperature range ²⁾		0 -40	25	85 85	°C
I	MP3 Decode	er (SC4 De-/Encoder)					
•	V _{SUPD1}	Digital supply voltage (MP3 decoder, G729 Decoder)	VDD	2.2	2.5	3.6	V
•	P _{MAX_D1}	MP3 Decoder (SC4 De-/Encoder)	VDD		80		mW
	T _C	Case Operating Temperature PLQFP64-1 PMQFP64-2 PQFN64-1			25 25 25	85 85 85	°C
	AAC Decode	er					
•	V _{SUPD2}	Digital supply voltage (G.729 A encoder/MP3 Decoder and SD Decryption/AAC Decoder)		2.5	2.7	3.6	
•	P _{MAX_D2}	AAC Decoder/G729 Encoder	VDD		122		mW
	T _C	Case Operating Temperature PLQFP64-1 PMQFP64-2 PQFN64-1			30 25 25	90 85 90	°C

A power-optimized board layout is recommended. The case operating temperatures mentioned in the "Recommended Operating Conditions" must not be exceeded at worst case conditions of the application. For turn-on voltage of DSP and codec, please refer to Section 2.10.2.1.

²⁾ Data sheet parameters are valid for "operating conditions" only. This product has been designed for and verified to the following temperature range: -40 °C to +85 °C. Design verification has been undertaken on samples processed with a specialized parameter set in order to confirm robustness to standard production process variations.

Symbol	Parameter	Pin Name	L	imit Value	s	Unit
			Min.	Тур.	Max.	
G729 Deco	der					
V _{SUPI2C}	I ² C bus supply voltage	I2CVDD	V _{SUPDn} 1) at VDD		3.9	V
P _{MAX_D3}	G.729 Decoder	VDD		50		mW
P _{MAX_A}	DAC-Headphone Playback	AVDD0/1		7		mW
T _C	Case Operating Temperature PLQFP64-1 PMQFP64-2 PQFN64-1			25 25 25	85 85 85	°C
V _{SUPx}	PIN supply voltage	XVDD	2.2	2.5	3.6	V
	PIN supply voltage in relation to digital supply voltage	7	0.62 × V _{SUPDn} 1)		1.6 × V _{SUPDn} 1)	V
V _{SUPA}	Analog audio supply voltage	AVDD0/1	2.2	2.7	3.6	V
	Analog audio supply voltage in relation to the digital supply voltage		0.62 × V _{SUPDn} 1)		1.6 × V _{SUPDn} 1)	V
V _{SUPDX}	Voltage differences within supply domains					V
1) n = 1 or 2	•	•			'	

Table 4–2: Reference Frequency Generation and Crystal Recommendation

Symbol	Parameter	Pin Name		Limit Values			
			Min.	Тур.	Max.		
External C	Clock Input Recommendations						
f _{CLK}	Clock frequency ¹⁾	XTI, XTO	13.00	18.432	20.00	MHz	
V _{CLKI}	Clock amplitude of external clock fed into XTI at $V_{AVDD} = 2.2 \text{ V}$	XTI	0.7		1.05	V _{PP}	
	Clock amplitude of external clock fed into XTI at $V_{AVDD} = 2.7 \text{ V}$		0.55		1.5		
	Clock amplitude of external clock fed into XTI at $V_{AVDD} = 3.3 \text{ V}$		0.45		1.75		
	Clock amplitude of external clock fed into XTO at $V_{AVDD} = 2.2 \text{ V}$	хто	1.25		2.2		
	Clock amplitude of external clock fed into XTO at $V_{AVDD} = 2.7 \text{ V}$		0.75		2.7		
	Clock amplitude of external clock fed into XTO at $V_{AVDD} = 3.3 \text{ V}$		0.55		3.3		
	Duty cycle	XTI, XTO	45	50	55	%	
Crystal Re	ecommendations			•		•	
f _P	Load resonance frequency at C _I = 20 pF	XTI, XTO		18.432		MHz	
Δf/f _S	Accuracy of frequency adjust- ment		-50		50	ppm	
Δf/f _S	Frequency variation vs. temperature		-50		50	ppm	
R _{EQ}	Equivalent series resistance			12	30	Ω	
	Shunt (parallel) capacitance			3	5	pF	

Table 4-3: Input clock frequency

Symbol	Parameter	Pin Name	Limit Values		S	Unit
			Min.	Тур.	Max.	
f _{CLK} 1)	G.729 Decoder G.729 Encoder	XTI, XTO	16.4 13.7			MHz MHz
	MPEG Decoder (SC4 En- Decoder)		11.0			MHz
1) Minimum F	CLK for SD-card decryption is define	ed in a supplement.		1		

Table 4-4: Input levels

Symbol	Parameter	Pin Name L	Limit Values		Unit	
			Min.	Тур.	Max.	
V _{IL}	Input low voltage	I2CC,			0.3	V
V _{IH}	Input high voltage	I2CD	1.4			٧
V _{IL}	Input low voltage	POR,			0.2	V
V _{IH}	Input high voltage	DCEN	0.9			V
V _{ILD}	Input low voltage	PI <i>,</i>			0.3	٧
V _{IHD}	Input high voltage	SI(B)I, SI(B)C, SI(B)D, PR, PCS, TE, DVS	V _{SUPx} -0.5			V

Table 4–5: Analog input and output recommendations

Symbol	Parameter	Pin Name		Limit Valu	ies	Unit
			Min.	Тур.	Max.	
Analog Refe	rence					
C _{AGNDC1}	Analog filter capacitor	AGNDC	1.0	3.3		μF
C _{AGNDC2}	Ceramic capacitor in parallel			10		nF
C _{PVDD}	Capacitor for analog circuitry	PVDD	3			nF
Analog Audi	o Inputs					
C _{inAD}	DC-decoupling capacitor at A/D-converter inputs	INL/R		390		nF
C _{inMI}	DC-decoupling capacitor at microphone-input	MICIN		390		nF
C _{LMICBI}	Minimum-Capacitance at microphone bias	MICBI	3.3			nF
Analog Audi	o Filter Outputs					
C _{FILT}	Filter capacitor for headphone amplifier high-Q type, NP0 or C0G material	FILTL/R OUTL/R	-20 %	470	+20 %	pF
Analog Audi	o Output					
Z _{AOL_HP}	Analog output load with stereo	OUTL/R	16			Ω
	headphones			100		pF
DC/DC-Conv	erter External Circuitry (please re	fer to application	n example)			
C ₁	VSENS blocking (<100 mΩ ESR)	VSENS1/2		330		μF
V _{TH}	Schottky diode threshold voltage	DCSO1/2 VSENS1/2	0.39			V
L	Ferrite core coil inductance	DCSO1/2		22		μH
S/PDIF Inter	face Analog Input			· · · · · · · · · · · · · · · · · · ·		
C _{SPI}	S/PDIF coupling capacitor	SPDI1/2 SPDIR		100		nF

4.6.2. Digital Characteristics

at T = T_A , V_{SUPD} , V_{SUPA} = 2.2 ... 3.6 V, $f_{Crystal}$ = 18.432 MHz, Typ. values for T_A = 25 °C in P(L/M)QFP package

Symbol	Parameter	Pin Name	Lin	nit Value	es	Unit	Test Conditions
			Min.	Тур.	Max.		
Digital Su	ipply Voltage						
I _{SUPD}	Current consumption	VDD, XVDD,		36		mA	2.2 V, sampling frequency ≥ 32 kHz
I _{SUPD}	Current consumption	I2CVDD		23		mA	2.2 V, sampling fre- quency ≤ 24 kHz
I _{SUPD}	Current consumption			15		mA	2.2 V, sampling frequency ≤ 12 kHz
I _{STANDBY}	Total current at stand-by				10	μА	DSP off, Codec off, DC/DC off, AD and DAC off, no I ² C access
Digital Ou	itputs and Inputs						
O _{DigL}	Output low voltage	PI <i>,</i>			0.3	V	I _{load} = 2 mA
O _{DigH}	Output low voltage	SOI, SOC, SOD, EOD, PRTR, PRTW, CLKO, SYNC, PUP, SPDO	V _{SUPx} –0.3			V	I _{load} = -2 mA
Z _{Digl}	Input impedance	ALL DIGITAL			7	pF	
I _{DLeak}	Digital input leakage cur- rent	INPUTS	-1		1	μΑ	0 V < V _{pin} < V _{SUPD}

4.6.2.1. I²C Characteristics

at T = 25°C, V_{SUPI2C} = 2.2...3.6 V in P(L/M)QFP package

Symbol	Parameter	Pin Name	Limit Values		Unit	Test Conditions	
			Min.	Тур.	Max.		
I ² C Input S	Specifications						
f _{I2C}	Upper limit I ² C bus frequency operation	I2CC	400			kHz	
t _{I2C1}	I ² C START condition setup time	I2CC, I2CD	300			ns	
t _{I2C2}	I ² C STOP condition setup time	12CC, 12CD	300			ns	
t _{I2C3}	I ² C clock low pulse time	I2CC	1250			ns	
t _{I2C4}	I ² C clock high pulse time	I2CC	1250			ns	
t _{I2C5}	I ² C data setup time before rising edge of clock	I2CC	80			ns	
t _{I2C6}	I ² C data hold time after falling edge of clock	I2CC	80			ns	
V _{I2COL}	I ² C output low voltage	12CC, 12CD			0.4	V	I _{load} = 3 mA
I _{I2COH}	I ² C output high leakage current	12CC, 12CD			1	μΑ	
t _{I2COL1}	I ² C data output hold time after falling edge of clock	12CC, 12CD	20			ns	
t _{I2COL2}	I ² C data output setup time before rising edge of clock	12CC, 12CD	250			ns	f _{I2C} = 400 kHz
V _{I2CIL}	I ² C input low voltage	I2CC, I2CD			0.3	V _{SUPI2C}	
V _{I2CIH}	I ² C input high voltage	I2CC, I2CD	0.6			V _{SUPI2C}	
t _W	Wait time	12CC, 12CD	0	0.5	4	ms	

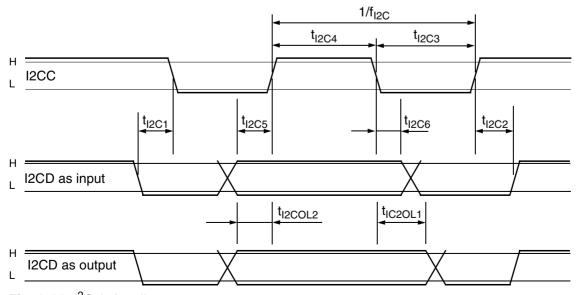


Fig. 4–20: I²C timing diagram

4.6.2.2. Serial (I²S) Input Interface Characteristics (SDI, SDIB)

at T = T_A , V_{SUPD} , V_{SUPA} = 2.2 ... 3.6 V, $f_{CRYSTAL}$ = 18.432 MHz, Typ. values for T_A = 25 °C in P(L/M)QFP package

Symbol	Parameter	Pin Name	Limit Values		Limit Values		Test Conditions
			Min.	Тур.	Max.		
†SICLK	I ² S clock input clock period	SI(B)C		325		ns	f _S = 48 kHz Stereo, 32 bits per sample (for demand mode see Table 4–6)
t _{SIDS}	I ² S data setup time before rising edge of clock (for continuous data stream: falling edge)	SI(B)C, SI(B)D	50			ns	
t _{SIDH}	I ² S data hold time	SI(B)D	50			ns	
t _{SIIS}	I ² S ident setup time before rising edge of clock (for continuous data stream: falling edge)	SI(B)C, SI(B)I	50			ns	
t _{SIIH}	I ² S ident hold time	SI(B)I	50			ns	
t _{bw}	Burst wait time	SI(B)C, SI(B)D	480				

Table 4–6: Maximum allowed sample clock frequency in Demand Mode

f _{Sample} (kHz)	f _C (MHz)	min. t _{SICLK} (ns)
48, 32	6.144	162
44.1	5.6448	177
24, 16	3.072	325
22.05	2.8224	354
12, 8	1.536	651
11.025	1.4112	708

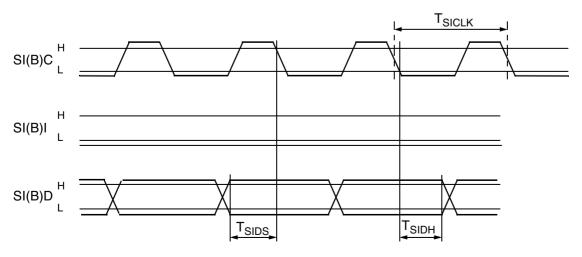


Fig. 4–21: Continuous data stream at serial input A or B. In this mode, the word strobe SI(B)I is not used and the data are read at the falling edge of the clock (bit[2] in D0:346 is set).

Table 4-7: Allowed transmission delays of external data source MPEG1/2 Layer 2/3

Symbol	Parameter	Pin Name	Li	Limit Values		Unit	Test Conditions
			Min.	Тур.	Max.		
t _{START48-320}	Allowed delay time before start of serial data	EOD			3.1	ms	48 kHz/s, 320 kbit/s
t _{START48-64}	transmission after assertion				5.7	ms	48 kHz/s, 64 kbit/s
t _{START24-320}	of signal at EOD				4.2	ms	24 kHz/s, 320 kbit/s
t _{START24-32}					9.2	ms	24 kHz/s, 32 kbit/s
t _{START12-64}					23.1	ms	12 kHz/s, 64 kbit/s
t _{START12-16}					25.6	ms	12 kHz/s, 16 kbit/s
t _{START8-64}					34.8	ms	8 kHz/s, 64 kbit/s
t _{START8-8}					38.4	ms	8 kHz/s, 8 kbit/s
^t stop	Allowed delay time before stop of serial data transmission after deassertion of signal at EOD	EOD			1.3	ms	Clock rate of input data 1 Mbit/s

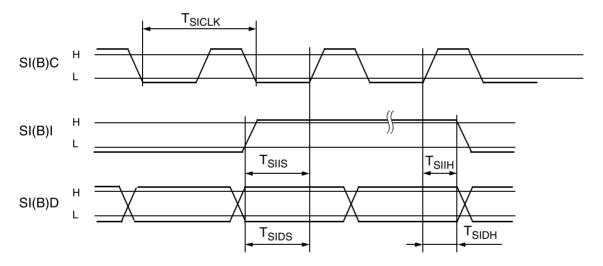


Fig. 4–22: Serial input of I²S signal

4.6.2.3. Serial Output Interface Characteristics (SDO)

at T = T_A , V_{SUPD} , V_{SUPA} = 2.2 ... 3.6 V, $f_{CRYSTAL}$ = 18.432 MHz, Typ. values for T_A = 25 °C in P(L/M)QFP package

Symbol	Parameter	Pin Name	Limit Values			Unit	Test Conditions
			Min.	Тур.	Max.		
t _{SOCLK}	I ² S clock output frequency	SOC		325		ns	f _S = 48 kHz Stereo 32 bits per sample
t _{SOISS}	I ² S word strobe delay time after falling edge of clock	SOC, SOI	0			ns	
t _{SOODC}	I ² S data delay time after falling edge of clock	SOC, SOD	0			ns	

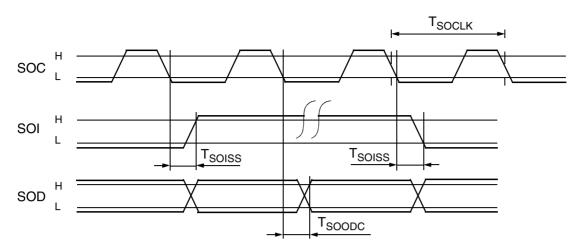


Fig. 4-23: Serial output interface timing

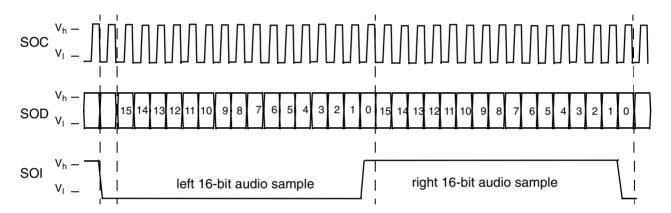


Fig. 4–24: Sample timing of the SDO interface in 16 bit/sample mode D0:346 settings are bit[14] = 0 (SOC not inverted)

bit[11] = 1 (SOI delay)

bit[5] = 0 (word strobe not inverted)

bit[4] = 1 (16 bits/sample)

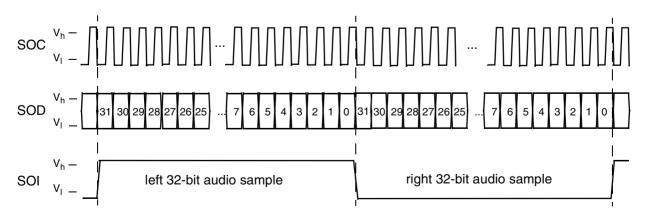


Fig. 4–25: Sample timing of the SDO interface in 32 bit/sample mode

D0:346 settings are

bit[14] = 0 (SOC not inverted)

bit[11] = 0 (no SOI delay)

bit[5] = 1 (word strobe inverted)

bit[4] = 0 (32 bits/sample)

4.6.2.4. S/PDIF Input Characteristics

at T = T_A , V_{SUPD} , V_{SUPA} = 2.2 ... 3.6 V, $f_{Crystal}$ = 18.432 MHz, Typ. values for T_A = 25 °C in P(L/M)QFP package.

Symbol	Parameter	Pin Name	Limit Values		Limit Values		Test Conditions
			Min.	Тур.	Max.		
V _S	Signal amplitude	SPDI1, SPDI2, SPDIR	200	500	1000	mV _{pp}	
f _{s1}	Bi-phase frequency	SPDI1, SPDI2, SPDIR		2.048		MHz	±1000 ppm, f _s = 48 kHz
f _{s2}	Bi-phase frequency	SPDI1, SPDI2, SPDIR		2.822		MHz	±1000 ppm, f _s = 44.1 kHz
f _{s3}	Bi-phase frequency	SPDI1, SPDI2, SPDIR		3.072		MHz	± 1000 ppm, f _s = 32 kHz
t _P	Bi-phase period	SPDI1, SPDI2, SPDIR		326		ns	at f _s = 48 kHz, (highest sampling rate)
t _R	Rise time	SPDI1, SPDI2, SPDIR	0		65	ns	at f _s = 48 kHz, (highest sampling rate)
t _F	Fall time	SPDI1, SPDI2, SPDIR	0		65	ns	at f _s = 48 kHz, (highest sampling rate)
	Duty cycle	SPDI	40	50	60	%	at bit value=1 and f _s = 48 kHz
t _{H1,L1}		SPDI	81		163	ns	minimum/maximum pulse duration with a level above 90 % or below 10 % and at f _s = 48 kHz
t _{Ho,Lo}		SPDI	163		244	ns	minimum/maximum pulse duration with a level above 90% or below 10% and at f _s = 48 kHz

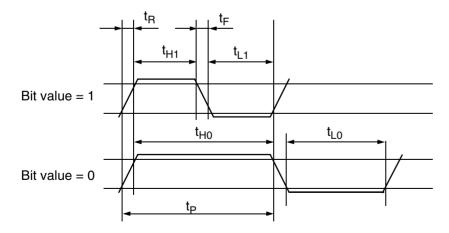


Fig. 4–26: Timing of the S/PDIF input

4.6.2.5. S/PDIF Output Characteristics

at T = T_A , V_{SUPD} , V_{SUPA} = 2.2 ... 3.6 V, $f_{CRYSTAL}$ = 18.432 MHz, Typ. values for T_A = 25 °C in P(L/M)QFP package.

Symbol	Parameter	Pin Name	L	Limit Values		Unit	Test Conditions
			Min.	Тур.	Max.		
f _{s1}	Bi-phase frequency	SPDO		3.072		MHz	f _s = 48 kHz
f _{s2}	Bi-phase frequency	SPDO		2.822		MHz	f _s = 44.1 kHz
f _{s3}	Bi-phase frequency	SPDO		2.048		MHz	f _s = 32 kHz
t _P	Bi-phase period	SPDO		326		ns	at f _s = 48 kHz, (highest sampling rate)
t _R	Rise time	SPDO	0		2	ns	C _{load} = 10 pF
t _F	Fall time	SPDO	0		2	ns	C _{load} = 10 pF
	Duty cycle	SPDO		50		%	
t _{H1,L1}		SPDO		163		ns	minimum/maximum pulse duration with a level above 90% or below 10% and at f _s = 48 kHz
t _{H0,L0}		SPDO		326		ns	minimum/maximum pulse duration with a level above 90% or below 10% and at f _s = 48 kHz
Vs	Signal amplitude	SPDO		V _{SUPD}			

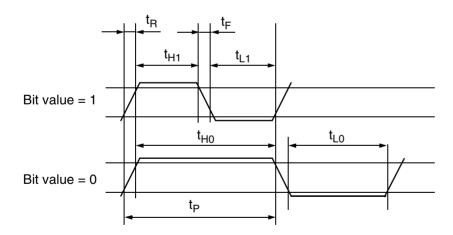


Fig. 4–27: Timing of the S/PDIF output

4.6.2.6. PIO as Parallel Input Interface: DMA Mode

In decoding mode, the data transfer can be started after the EOD pin of the MAS 35x9F is set to "high". After verifying this, the controller signalizes the sending of data by activating the PR line. The MAS 35x9F responds by setting the RTR line to the "low" level. The MAS 35x9F reads the data PI[19:12] and sets RTR to low after rising edge of PR. After RTR is set to high, the mC sets PR to low. The next data word write operation will be initialized again by setting the PR line via

the controller. Please refer to Figure for the exact timing.

The procedure abo<u>ve</u> will be repeated until the MAS 35x9F sets the EOD signal to "0" which indicates that the transfer of one data block has been executed. Subsequently, the controller should set PR to "0", wait until EOD rises again and then repeat the procedure to send the next block of data. The DMA buffer for MPEG decoding is 30 bytes long. The size for G.729 is 10 bytes.

Table 4-8: PIO input DMA mode timing

Symbol	Pin Name	Min.	Max.			
t _{st}	PR, EOD	10 ns	2000 μs			
t _r	PR, RTR		t_clm			
t _{set1}	PI[19:12]		2×t_clm- 33 ns			
t _{set2}	PI[19:12]	dep. on appl.				
t _h	PI[19:12]	5×t_ clm				
t _{rtrq}	RTR	5×t_ clm	MP3: 60×t_clm AAC: 140×t_clm			
t _{pr}	PR	5×t_ clm				
t _{rpr}	PR, RTR	t_clm				
t _{eod}	PR, EOD	t_clm				
t _{eodq}	EOD	150×t_clm ¹⁾	200 ms ¹⁾			
1) See Parallel I/O Application Note,						

Order no. 6251-590-2-11C.

Table 4-9: t_clm in MP3

Sample rate [kHz]	t_clm [ns]	f_clm [MHz]
48 or 32	41	24.5760
44.1	44	22.5792
24 or 16	81	12.2880
22.05	89	11.2896
12 or 8	163	6.1440
11.025	177	5.6448

Table 4-10: t_clm in AAC

Sample rate [kHz]	t_clm [ns]	f_clm [MHz]
48 or 32	33	30.720
44.1	35	28.224
24 or 16	65	15.360
22.05	71	14.112
12 or 8	130	7.680
11.025	142	7.056

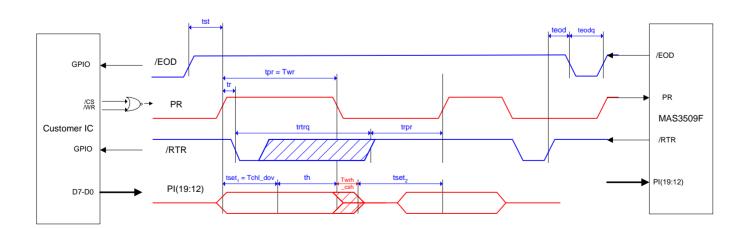


Fig. 4–28: Handshake protocol for writing MPEG data to the PIO-DMA

4.6.2.7. PIO as Parallel Input Interface: Program Download Mode

Handshake for PIO input in Program Download Mode is accomplished through the RTR, PCS, and PI12..PI19 signal lines (see Fig. 4–29). The PR line should be set to low level.

The MAS 35x9F will drive RTR low as soon as it is ready to receive a byte and RTR will stay low until one byte has been written. Writing of a byte is performed with a PCS pulse, driven by the microcontroller. The MAS 35x9F reads data after the falling edge of PCS and will finish the cycle by setting RTR to high level after the rising edge of PCS. The next data transfer is initialized by the MAS 35x9F by driving the RTR line.

Table 4-11: PIO Program Download Mode timing

Symbol	Pin	Min.	Max.	Unit
t ₀	$\overline{RTR}, \overline{PCS}$	0		μs
t ₁	PCS	150		ns
t ₂	$\overline{PCS}, \overline{RTR}$	0	30	ns
t ₃	RTR	0.4	5	μs
t ₄	PI	50		ns
t ₅	PI	50		ns

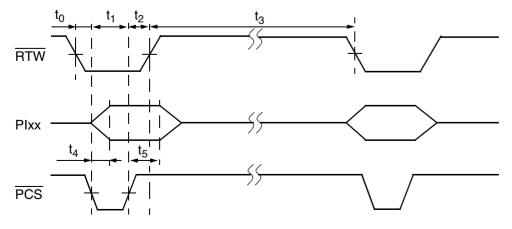


Fig. 4-29: PIO program download mode timing

4.6.2.8. PIO as Parallel Output Interface

Some downloadable software may use the PIO interface (lines PI19...PI12) as output. The data transfer rate and conditions are defines by the software function.

Handshaking for PIO output mode is accomplished through the RTW, PCS, and PI12..PI19 signal lines (see Fig. 4–30). The PR line has to be set to high level.

RTW will go low as soon as a byte is available in the output buffer and will stay low until a byte has been read. Reading of a byte is performed with a PCS pulse. Data is latched out from the MAS on the falling edge of PCS and removed from the bus on the rising edge of PCS.

Table 4-12: PIO output mode timing

Symbol	Pin	Min.	Max.	Unit
t _O	RTW, PCS	0.010	1800	μs
t ₁	PCS	0.330		μs
t ₂	$\overline{PCS}, \overline{RTW}$	0.010		μs
t ₃	RTW	0.330	10000	μs
t ₄	PI	0.330		μs
t ₅	PI	0.081		μs

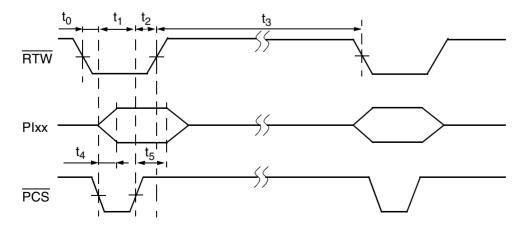


Fig. 4-30: Output timing

4.6.3. Analog Characteristics

at T = T_A , V_{SUPDn} , V_{SUPx} = 2.2 to 3.6 V, V_{SUPA} = 2.2 to 3.6 V, $f_{CRYSTAL}$ = 13 to 20 MHz, typical values at T_A = 25 °C and $f_{CRYSTAL}$ = 18.432 MHz in P(L/M)QFP package

Symbol	Parameter	Pin Name	Li	imit Valu	es	Unit	Test Cor	nditions
			Min.	Тур.	Max.			
Analog Sup	oply	•		•		•	•	
I _{AVDD}	Current consumption analog audio	AVDD0/1		5		mA	V _{SUPA} =	2.2 V, Mute
I _{QOSC}	Current consumption crystal oscillator	AVDD0/1		200		μА	Codec = DSP = of DC/DC =	ff
I _{STANDBY}					10		Codec = DSP = of DC/DC =	ff
Crystal Osc	cillator							
V _{DCCLK}	DC voltage at oscillator pins	XTI, XTO		0.5		V _{SUPA}		
V _{ACLK}	Clock amplitude		0.5		V _{SUPA} -0.5	V _{PP}	if crystal	is used
C _{IN}	Input capacitance			3		pF		
R _{OUT}	Output resistance	XTO		220		Ω	V _{SUPA} =	2.2 V
				125			V _{SUPA} =	2.7 V
				94			V _{SUPA} =	3.3 V
Analog Ref	erence							
V _{AGNDC}	Analog Reference Voltage	AGNDC				V	R _L >> 10	MΩ, to VREF
							V _{SUPA}	bits[15], [14] in register 6A _{hex}
				1.1			>2.2 V	00
				1.3			>2.4 V	01
				1.6			>3.0 V	10
V _{MICBI}	Bias voltage for microphone	MICBI					V _{SUPA}	bits[15], [14] in register 6A _{hex}
				1.8			>2.2 V	00
				2.13			>2.4 V	01
				2.62			>3.0 V	10
R _{MICBI}	Source resistance	MICBI		180		Ω		
I _{MAX}	Maximum current microphone bias	MICBI				μА	V _{SUPA}	bits[15], [14] in register 6A _{hex}
				300			>2.2 V	00

Symbol	Parameter	Pin Name	L	Limit Values			Test Conditions
			Min.	Тур.	Max.		
Analog Au	dio Input						
V _{AI}	Analog line input clipping level (at minimum analog input gain, i.e. –3 dB)	INL/R				V _{pp}	V _{SUPA} bits[15], [14] in register 6A _{hex}
				2.2			>2.2 V 00
				2.6			>2.4 V 01
				3.2			>3.0 V 10
V _{MI}	Microphone input clipping level (at minimum analog	MICIN				mV_{pp}	V _{SUPA} bits[15], [14] in register 6A _{hex}
	input gain, i.e. +21 dB)			141			>2.0 V 00
				167			>2.4 V 01
				282			>3.0 V 10
R _{inAl}	Analog line input resistance	INL/R		97		kΩ	at minimum analog input gain, i.e3 dB
				20			at maximum analog input gain, i.e. +19.5 dB
				67			not selected
R _{inMI}	Microphone input resistance	MICIN		94		kΩ	at minimum analog input gain, i.e. –21 dB
				8			at maximum analog input gain, i.e. +43.5 dB
				94			not selected
SNR _{AI}	Signal-to-noise ratio of line input	INL/R		74		dB(A)	BW = 20 Hz20 kHz, analog gain = 0 dB, input 1 kHz at V _{AI} –20 dB
SNR _{MI}	Signal-to-noise ratio of microphone input	MICIN		73		dB(A)	BW = 20 Hz20 kHz, analog gain = +21 dB, input 1 kHz at V _{MI} -20 dB
THD _{AI}	Total harmonic distortion of analog inputs	INL/R MICIN		0.01	0.02	%	BW = 20 Hz20 kHz, analog gain = 0 dB, resp. 24 dB, input 1 kHz at -3 dBFS = V _{AI} -6 dB resp. V _{MI} -6 dB
XTALK _{AI}	Crosstalk attenuation left/right channel (analog inputs)	INL/R MICIN		80		dB	f = 1 kHz, sine wave, analog gain = 0 dB, input = -3 dBFS
PSRR _{AI}	Power supply rejection ratio for analog audio inputs	AVDD0/1, INL/R MICIN		45		dB	1 kHz sine at 100 mV _{rms}
				20		dB	≤100 kHz sine at 100 mV _{rms}

Symbol	Parameter	Pin Name	L	Limit Values			Test Conditions
			Min.	Тур.	Max.		
Audio Outp	ut						
V _{AO1}	Analog output voltage AC	OUTL/R					$\begin{aligned} R_L \ge &1 \ k\Omega \\ &\text{input} = 0 \ dBFS \ digital } \\ V_{SUPA} & \text{bits[15], [14] in} \\ & \text{register } 6A_{hex} \end{aligned}$
	at 0 dB output gain			1.56		V_{pp}	>2.2 V 00
				1.84			>2.4 V 01
				2.27			>3.0 V 10
	at +3 dB output gain			2.20		V_{pp}	>2.2 V 00
				2.60			>2.6 V 01
				3.20			>3.2 V 10
dV _{AO1}	Deviation of DC-level at analog output for AGNDC-Voltage	OUTL/R	-20		20	mV	
V _{AO2}	Analog output voltage AC	OUTL/R					R_L is 16 Ω headphone and 22 Ω series resistor Input = 0 dBFS digital
							(see Fig. 5-1 on page 89)
							V _{SUPA} bits[15], [14] in register 6A _{hex}
	at 0 dB output gain			1.56		V _{pp}	>2.2 V 00
				1.84			>2.4 V 01
				2.27			>3.0 V 10
	at +3 dB output gain			2.00		V _{pp}	>2.2 V 00
				2.40			>2.6 V 01
				3.00			>3.2 V 10
R _{outAO}	Analog output resistance	OUTL/R			6	Ω	analog gain = +3 dB, input = 0 dBFS digital
SNR _{AO}	Signal-to-noise ratio of analog output	OUTL/R		94		dB(A)	R_L ≥16 Ω BW = 20 Hz20 kHz, analog gain = 0 dB input = −20 dBFS
THD _{AO}	Total harmonic distortion (headphone)	OUTL/R		0.03	0.05	%	for $R_L \ge 16 \Omega$ plus 22 Ω series resistor (see Fig. 5–1 on page 89)
				0.003	0.01		for R _L ≥ 1 kΩ
Lev _{MuteAO}	Mute level	OUTL/R		-113		dBV	A-weighted BW = 20 Hz22 kHz, no digital input signal,

Symbol	Parameter	Pin Name	Limit Values			Unit	Test Conditions
			Min.	Тур.	Max.		
XTALK _{AO}	Crosstalk attenuation left/right channel (headphone)	OUTLR		80		dB	f=1 kHz, sine wave, OUTL/R: $R_L \ge 16 \Omega$ (see Fig. 5–1 on page 89) analog gain = 0 dB input = -3 dBFS
PSRR _{AO}	Power supply rejection ratio	AVDD0/1		70		dB	1 kHz sine at 100 mV _{rms}
	for analog audio outputs	OUTL/R		35		dB	≤100 kHz sine at 100 mV _{rms}

4.6.4. DC/DC Converter Characteristics

at T = T_A , V_{in} = 1.2 V, V_{outn} = 3.0 V, f_{clk} = 18.432 MHz, f_{sw} = 384 kHz, PWM mode, L = 22 μ H, in P(L/M)QFP package (unless otherwise noted) Typ. values for T_A = 25 $^{\circ}$ C

Symbol	Parameter	Pin Name	L	Limit Values		Unit	Test Conditions
			Min.	Тур.	Max.		
V _{IN}	Minimum start-up input voltage			0.9		V	I _{LOAD} ≤ 1 mA, DCCF = 5050 _{hex} (reset)
V _{IN}	Minimum operating input voltage						1)
	DC1 DC2			0.7 0.8		V	I _{LOAD} = 50 mA, DCCF = 5050 _{hex} (reset)
	DC1 DC2			1.1 1.2		V	I _{LOAD} = 200 mA, DCCF = 5050 _{hex} (reset)
V _{OUT}	Programmable output voltage range	VSENSn	2.0		3.5	V	Voltage settings in DCCF register (I ² C subaddress 76 _{hex})
V _{OTOL}	Output voltage tolerance	VSENSn	-4		4	%	$I_{LOAD} = 20 \text{ mA}$ $T_A = 25 {}^{\circ}\text{C}^{2)}$
I _{LOAD1}	Output current 1 battery cell	VSENSn			200	mA	V _{IN} = 0.91.5 V, 330 μF
I _{LOAD2}	Output current 2 battery cells				600	mA	V _{IN} = 1.83.0 V, 330 μF
dV _{OUT} / dV _{IN} /V _{OUT}	Line regulation	VSENSn		0.7		%/V	I _{LOAD} = 20 mA
dV _{OUT} / V _{OUT}	Load regulation	VSENSn		-1.8		%	I _{LOAD} = 20200 mA,
h _{max}	Maximum efficiency				95	%	V _{IN} = 2.4 V, V _{OUT} = 3.5 V
f _{switch}	Switching frequency	DCSOn	297	384	576	kHz	(see Section 2.6.2. on page 12), (see Table 3–3)
f _{startup}	Switching frequency during start-up	DCSOn		250		kHz	VSENSn < 1.9 V

 $^{^{1)}}$ Since the regulators are bootstrapped, once started they will operate down to 0.7 V input voltage $^{2)}$ PFM mode regulates approx. 1% higher

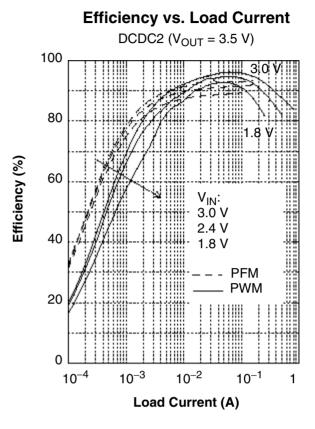
Symbol	Parameter	Pin Name	Limit Values		Unit	Test Conditions	
			Min.	Тур.	Max.		
I _{supPFM1}	Supply current in PFM mode	VSENS1		75		μА	3)
I _{supPFM2}		VSENS2		135			
I _{supPWM1}	Supply current in PWM mode	VSENS1		265		μΑ	VSENSn
I _{supPWM2}		VSENS2		325			4)
I _{Inmax}	NMOS switch current limit	DCSOn, DCSGn		1		Α	PWM-Mode
	(low side switch)			0.4		Α	PFM-Mode
I _{Iptoff}	PMOS switch turnoff current (rectifier switch)	DCSOn VSENSn		70		mA	
R _{on}	NMOS switch on Resistance (low side switch)	DCSO1, DCSG1		170		mΩ	
		DCSO2, DCSG2		280		mΩ	
I _{LEAK}	Leakage current	DCSOn, DCSGn		0.1		μΑ	Converter off, no load

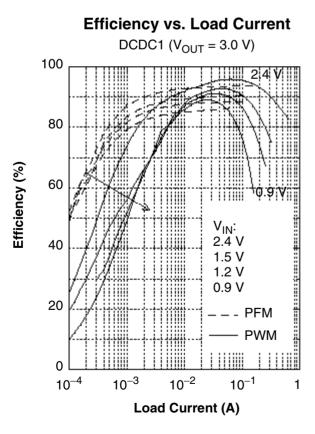
³⁾ Current into VSENSn Pin. VIN > VOUT + 0.4 V; no DC/DC-Converter switching action present 4) Add. current of oscillator at PIN AVDD0/1, (see Section 4.6.3. on page 81)

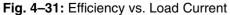
MAS 35x9F

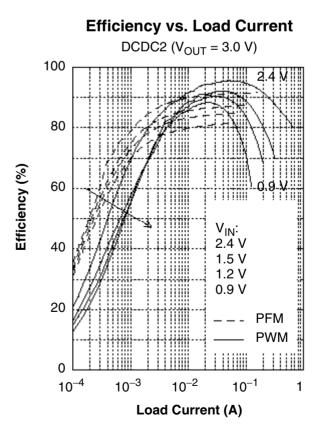
4.6.5. Typical Performance Characteristics

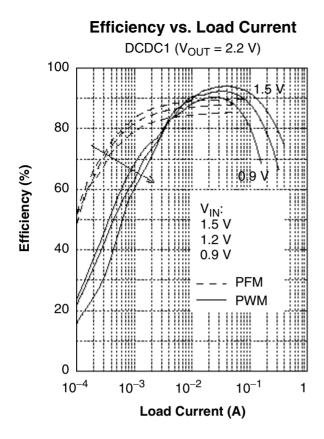
Efficiency vs. Load Current DCDC1 (V_{OUT} = 3.5 V) 80 80 V_{IN}: 3.0 V 2.4 V 1.8 V 1.8 V ---- PFM PWM 20 10⁻⁴ 10⁻³ 10⁻² 10⁻¹ 1 Load Current (A)

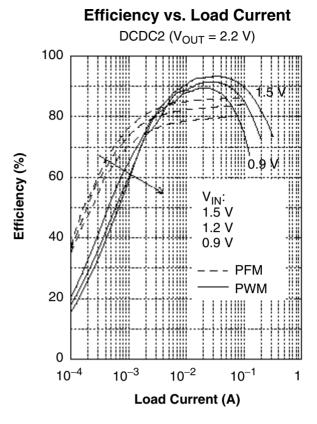


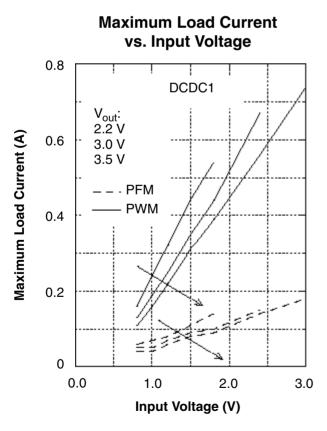












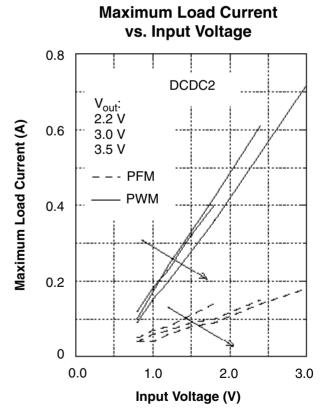
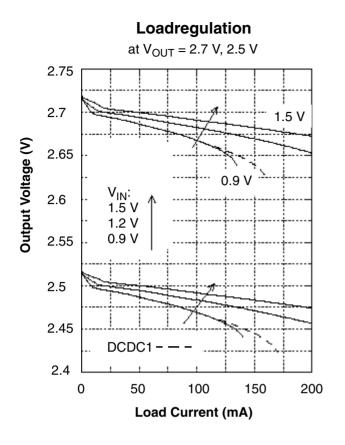
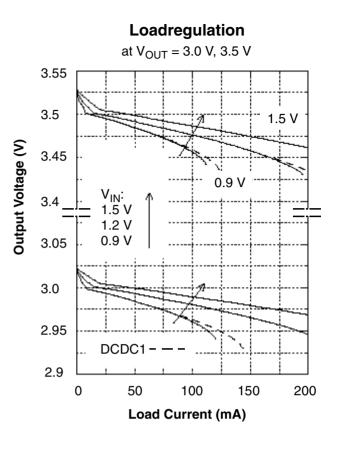


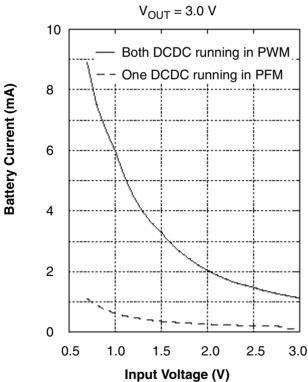
Fig. 4-32: Maximum Load Current vs. Input Voltag

Note: Efficiency is measured as $V_{SENSn} \times I_{LOAD} / (V_{in} \times I_{in})$. I_{AVDD} is not included (Oscillator current)









5. Application

5.1. Typical Application in a Portable Player

- MMC/SDI-Card or SMC/CF2+ used as storage media
- Dashed lines show optional (external) devices

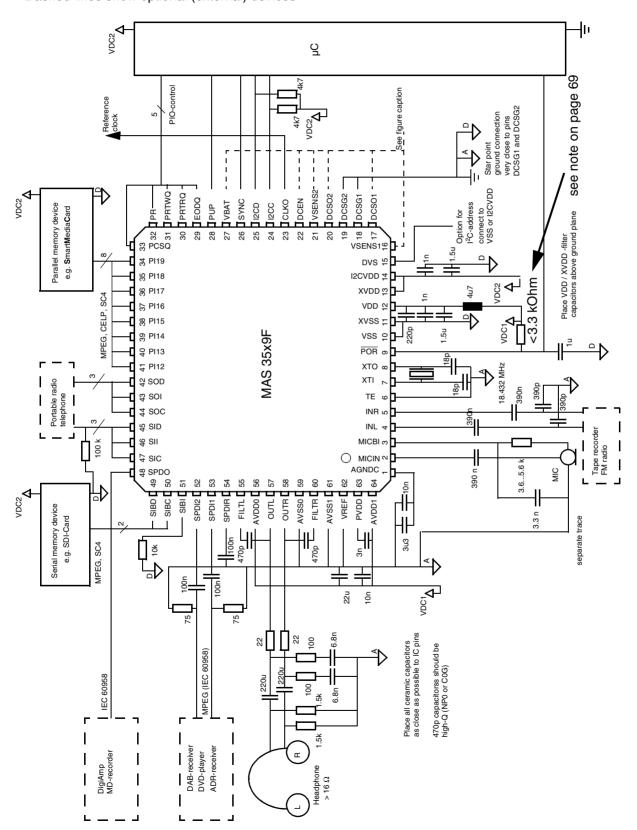


Fig. 5–1: Application circuit of the MAS 35x9F. For connections of the DC/DC converters, please refer to Fig. 5–2.

5.2. Recommended DC/DC Converter Application Circuit

(Power optimized scenario, (see Fig. 2-7 on page 13)).

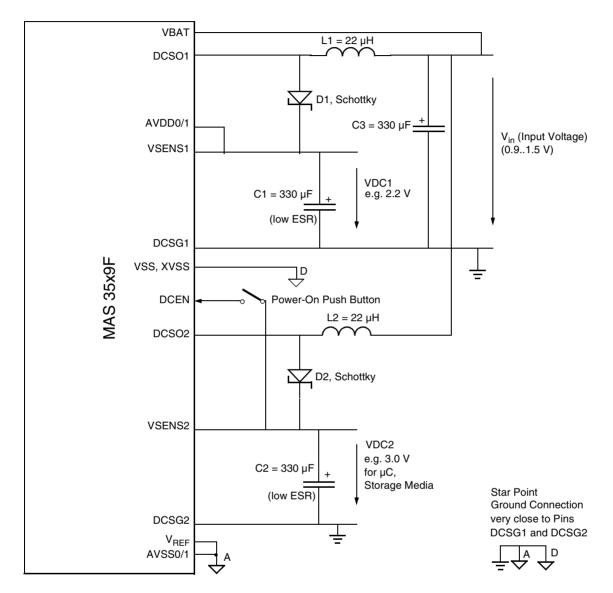


Fig. 5-2: External circuitry for the DC/DC converters

For turn-on voltage of DSP and codec, please refer to Section 2.10.2.1.

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MAS 35x9F

6. Data Sheet History

- Preliminary data sheet: "MAS 35x9F, MPEG Layer 2/3, AAC Audio Decoder, G.729 Annex A Codec", Aug. 01, 2001, 6251-505-1PD. First release of the preliminary data sheet.
- 2. Data Sheet: "MAS 35X9F MPEG Layer 2/3, AAC Audio Decoder, G.729 Annex A Codec", June 30, 2004, 6251-505-1DS. First release of the data sheet.
- Data Sheet: "MAS 35X9F MPEG Layer 2/3, AAC Audio Decoder, G.729 Annex A Codec", July 1, 2005, 6251-505-2DS. Second release of the data sheet. Major changes:
- New package diagrams were included for PLQFP64-1, PMQFP64-2, PQFN64-1
- Functional description of the MP3 Block Input Mode now available for improved input timing behavior of the MPEG 1/2/2.5 Layer3 decoder
- Important advice for turn-on and operating voltage
- Changes in configuration registers
- Tables were added: PIO input DMA mode timing;
 Sample rate in MP3; Sample rate in AAC
- Handshake protocol for writing MPEG data to the PIO-DMA was added.

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